(Limiting Supplies. For Development Only.)

The HD63701X0 is a high performance 8-bit CMOS single chip microcomputer unit (MCU) which, including 4k bytes of EPROM, is object code compatible with the HD6301X0.

The HD63701X0 contains 4k bytes of EPROM, 192 bytes of RAM, serial communication interface and 53 parallel I/O pins in addition to CPU. It includes functions of halt, memory ready, low speed access and releasing external bus for system expansion.

The HD 63701X0 is available in a hermetically sealed 64-pin shrunk ceramic package which includes a glass window that allows for programming and EPROM crasure in the same way as 2732A type EPROM.

■ FEATURES

- Instruction Set Compatible with the HD6301X0 and 6801
- 4k Bytes of EPROM (compatible with 2732A type)
- 192 Bytes of RAM
- 53 Parallel I/O Pins
 - 24 I/O Common Pins (Port 2, 3, 6)
 - 21 Output Pins (Port 1, 4, 7)
- 8 Input Pins (Port 5)
- Driving Darlington Transistor (Port 2, 6)
- 16-bit Programmable Timer
- Input Capture Register x 1
- Free Running Counter x 1
- Output Compare Register x 2
- 8-bit Reloadable Timer
 - External Event Count
 - External Event Count Spare Wave Generation
- Serial Communication Interface (SCI)
 - Asynchronous Mode/Clock Synchronous Mode
 - 3 Transfer Formats (Asynchronous Mode)
- 6 Clock Sources
- Memory Ready for Low Speed Memory Access
- Halt
- Error-Detection (Address Error, Op-code Error)
- Interrupts 3 External, 7 Internal
- Operation Mode

MCU Mode 1 -- Expanded (Internal ROM Inhibited)
Mode 2 -- Expanded (Internal ROM Valid)
Mode 3 -- Single-chip Mode

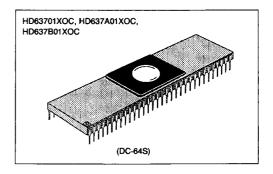
EPROM Mode

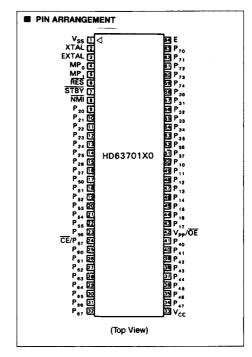
- Up to 65k Bytes of Address Space
- Low Power Dissipation Mode
 - Sleep
 - Standby
- Minimum Instruction Execution Time 0.5μs (f=2.0MHz)
- Wide Operation Range

 $V_{CC}=5V\pm10\% \begin{cases} f=0.5 \text{ to } 1.0MHz; HD63701X0 \\ f=0.5 \text{ to } 1.5MHz; HD637A01X0 \\ f=0.5 \text{ to } 2.0MHz; HD637B01X0 \end{cases}$

[Precautions on using EPROM On-chip Single-chip Microcomputer]

- (1) If the MCU is exposed to strong light especially a fluorescent lamp or the sunlight, EPROM data may be erased or the MCU may malfunction by photocurrent. Therefore, after programming, it is suggested that applications which expose the LSI to ambient light may require an opaque label over the window.
- (2) Do not rub the window with materials like plastics, or do not touch a charged body on the window. Electro static charge may adversely affect the functionality of the LSI. A conductive opaque label, suggested above, is effective on distributing charge equally.

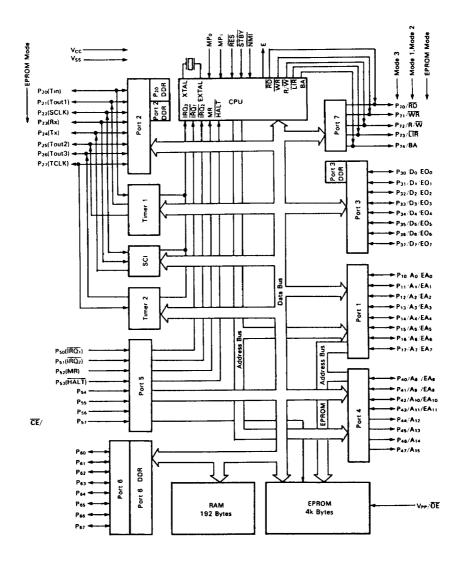




■ PROGRAM DEVELOPMENT SUPPORT TOOLS

- Cross assembler and C compiler software for IBM PCs and compatibles
- In circuit emulator for use with IBM PCs and compatibles
- Programming socket adapter for programming the EPROM-on-chip device.

■ BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc}	-0.3 ~ +7.0	V
Program Voltage	V _{PP}	-0.3~ +22	V
Input Voltage	V _{in}	-0.3 ~ V _{CC} +0.3	٧
Operating Temperature	Topr	0~+70	°c
Storage Temperature	T _{stg}	-55 ~ +125	°C

(Note) This product has protection circuits in input terminal from high static electricity voltage and high electric field. But be careful not to apply overvoltage more than maximum ratings to these high input impedance protection circuits. To assure the normal operation, we recommend Vin, Vout: VSS≤ (Vin or Vout)≤ VCC.

ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (V_{CC} = 5V ± 10%, f = 0.1 to 2.0 MHz, V_{SS} = V_{PP} = 0V, Ta = -20 ~ + 70°C, unless otherwise noted).

Item	١	Symbol	Test Condition	min	typ	max	Unit
	RES, STBY, MP0, MP1			V _{CC} -0.5			
Input "High" Voltage	EXTAL	ViH		V _{CC} x0.7	-	V _{CC} +0.3	V
input riigii voltage		* 1H				VCC 10.3	*
	Other Inputs			2.0			
Input "Low" Voltage	All Inputs	V _{IL}		-0.3	l	8.0	V
Input Leakage Current	NMI, RES, STBY, MPo, MP1, Port 5	l _{in}	V_{in} =0.5 \sim V_{CC} -0.5 V	_	-	1.0	μΑ
Three State (off-state) Leakage Current	Ports 1, 2, 3, 4, 6, 7	I _{TSI}	V _{in} =0.5 ~ V _{CC} -0.5V	_	_	1.0	μΑ
Output "High" Voltage	All Outputs	.,	I _{OH} =-200μA	2.4	_	_	٧
	All Outputs	V _{OH}	I _{OH} =-10μA	V _{CC} -0.7		_	٧
0	/ \/ ata		I =1.6==A				
Output "Low" Voltage	All Outputs	V _{OL}	I _{OL} =1.6mA	_	-	0.4	V
Darlington Drive Current		-lon	V _{ou1} =1.5V	1.0	_	10.0	mA
Input Capacitance	All Inputs (Except V _{PP} /OE)	C _{in}	V _{in} =0V, f=1MHz, Ta=25°C	_	-	12.5	pF
	V _{PP} /OE		1a=25 C	_	l –	25.0	pF
Standby Current	Non Operation	I _{STB}		-	3.0	15.0	μА
	<u> </u>		Sleeping (f=1MHz**)	1 –	1.5	3.0	mA
		SLP	Sleeping (f=1.5MHz**)	_	2.3	4.5	mA
Current Dissipation*			Sleeping (f=2MHz**)		3.0	6.0	mA
Current Dissipation*		Operating (f=1MHz**)	_	7.0	10.0	mA	
	l _{CC}	Operating (f=1.5MHz**)		10,5	15.0	mA	
			Operating (f=2MHz**)		14.0	20.0	mA
RAM Standby Voltage		VRAM		2.0		_	V

^{*}VIH min = VCC-1.0V, VIL max = 0.8V (All output terminals are at no load.)

typ. value (f = X MHz) = typ. value (f = 1MHz) × X max. value (f = X MHz) = max. value (f = 1MHz) × X (both the sleeping and operating)

^{**}Current Dissipation of the operating or sleeping condition is proportional to the operating frequency. So the typ. or max, values about Current Dissipations at x MHz operation are decided according to the following formula;

• AC CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, f = 0.1 to 2.0 MHz, $V_{SS} = V_{PP} = 0V$, Ta = 0 $\sim +70$ °C, unless otherwise noted).

BUS TIMING

			Test	HD	63701	XO	HD	637A01	X0	HD	637B01	X0	Unit
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	——
Cycle Time		t _{cyc}		1	-	10	0.666	_	10	0.5		10	μs
Enable Rise Time		ter		-	-	25		-	25	-		25	ns
Enable Fall Time		ter		_	_	25		_	25		_	25	ns
Enable Pulse Width "Hi	ole Pulse Width "High" Level*			450	-	-	300	1	-	220		_	ns
Enable Pulse Width "Lo	w" Level*	PWEL		450		-	300	-		220			ns
Address, R/W Delay Tir	ne*	t _{AD}	1	-	-	250			190			160	n:
Data Delay Time	Write	t _{DDW}				200	_		160			120	n
Data Set-up Time	Read	tosa	Fig. 1	80	_		70		-	70	-		n
Address, R/W Hold Tim	ne*	tan	"ig. i	70	_	_	45			30			n
	Write*	t _{HW}	1	70	-		50			35			n:
Data Hold Time	Read	tHR		0			0		-	0			n
RD, WR Pulse Width*		PWRW		450			300	_		220			n
RD, WR Delay Time		TRWD	1	_	-	40			40	-		40	n
RD, WR Hold Time		tHRW	1	_	-	30			30	-	-	25	n
LIR Delay Time		TOLR	1	_		200		_	160	<u> </u>	-	120	n
LIR Hold Time		tHLR	1	10	-	Ι =	10	-	-	10		<u> </u>	n
MR Set-up Time*		tsmr		400	-		280			230	<u> </u>	<u> </u>	n
MR Hold Time*		tHMR	Fig. 2	-	-	90	_		40		_	0	n
E Clock Pulse Width at	MR	PWEMR	Ī	<u> </u>		9			9			9	μ
Processor Control Set-u	ıp Time	t _{PCS}	Fig. 3, 10, 11	200			200	_	_	200			n
Processor Control Rise Time		t _{PCr}	F:- 2.2	_		100	<u>l -</u>		100			100	n
Processor Control Fall Time		tpcf	Fig. 2, 3	_	_	100			100			100	n
BA Delay Time		tBA	Fig. 3	T-	-	250	-		190			160	
Oscillator Stabilization	Time	tac	Fig. 11	20	-	<u> </u>	20		<u> </u>	20			п
Reset Pulse Width		PWast		3	-	_	3	-] -	3	l		tc

These timings change in approximate proportion to t_{CYC}. These figures characteristically represent those when t_{CYC} is minimum (= in the highest speed operation).

PERIPHERAL PORT TIMING

				. Test		063701	X0	HD637A01X0			HD637B01X0			Unit
lte	m		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Onit
Peripheral Data Set-up Time	Ports	2, 3, 5, 6	t _{PDSU}	Fig. 5	200			200	_	-	200	-	_	ns
Peripheral Data Hold Time	Ports	2, 3, 5, 6	^t PDH	Fig. 5	200	_	_	200	_		200	-		ns
Delay Time (Enal positive Transitio Peripheral Data V	n to	Ports 1, 2, 3, 4, 6, 7	t _{PWED}	Fig. 6	-	-	300	-		300	-	-	300	ns

TIMER, SCI TIMING

1	tem	Symbol	Test	н	63701	X0	н	D637A0)1 X O	HD	637B01	X0	11-:4
· · · · · · · · · · · · · · · · · · ·	reili	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Timer 1 Input	t Pulse Width	t _{PWT}	Fig. 8	2.0	-	-	2.0	-	-	2.0	-	1	t _{cyc}
Delay Time (Enable Positive Transition to Timer Output)		t _{TOD}	Fig. 7	-	-	400	-	-	400	_	-	400	ns
SCI Input	Async. Mode		Fig. 8	1.0	-	_	1.0	_	-	1.0	_	_	t _{cyc}
Clock Cycle	Clock Sync.	t _{Scyc}	Fig. 4, B	2.0	-	_	2.0	_	-	2.0	-	-	t _{cyc}
SCI Transmit Time (Clock S		t _{TXD}		-	-	200	-	-	200	-	-	200	ns
SCI Receive D Time (Clock S		t _{SRX} Fig. 4		290	-	-	290	-	-	290	-	-	ns
SCI Receive D (Clock Sync. I)ata Hold Time Mode)	t _{HRX}		100	_	_	100	-	-	100	-	_	ns
SCI Input Clo	ck Pulse Width	t _{PWSCK}		0.4	-	0.6	0.4	_	0.6	0.4	-	0.6	t _{Scyc}
Timer 2 Input	Clock Cycle	t _{tcyc}	1	2.0	_		2.0	_		2.0	-	-	t _{cyc}
Timer 2 Input Width	Clock Pulse	†PWTCK	Fig. 8	200		-	200	-	-	200	-	-	ns
Timer 1·2, SC Rise Time	I Input Clock	† _{CKr}		-	-	100	-	_	100	-	_	100	ns
Timer 1·2, SC Fall Time	I Input Clock	t _{CKf}		-	-	100	+	-	100	_	-	100	ns

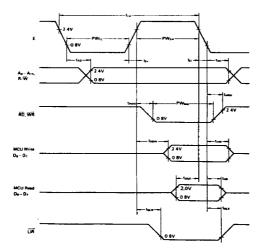


Figure 1 Mode 1, Mode 2 Bus Timing

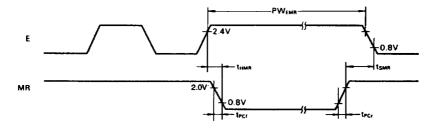


Figure 2 Memory Ready and E Clock Timing

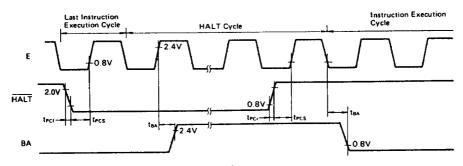


Figure 3 HALT and BA Timing

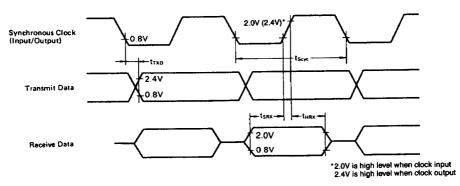


Figure 4 SCI Clocked Synchronous Timing

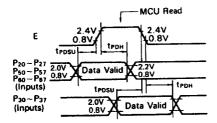


Figure 5 Port Data Set-up and Hold Times (MCU Read)

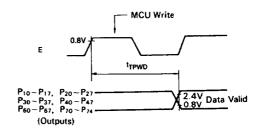
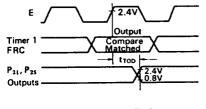
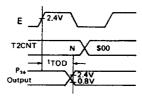


Figure 6 Port Data Delay Times (MCU Write)



(a) Timer 1 Output Timing



(b) Timer 2 Output Timing

Figure 7 Timer Output Timing

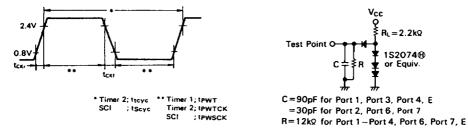


Figure 8 Timer 1-2, SCI Input Clock Timing

Figure 9 Bus Timing Test Loads (TTL Load)

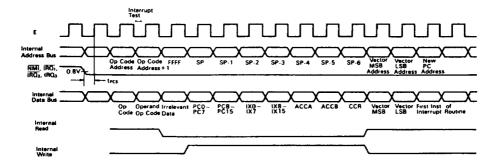


Figure 10 Interrupt Sequence

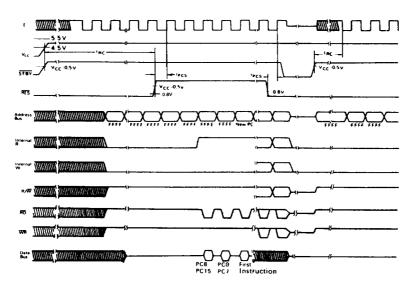


Figure 11 Reset Timing

- EPROM PROGRAMMING ELECTRICAL CHARACTERISTICS
- DC CHARACTERISTICS (V_{CC}=5V±5%, V_{PP}=21V±0.5V, V_{SS}=0V, Ta=25°C±5°C, unless otherwise noted.)

Item	Symbol	Test Condition	min	typ	max	Unit
Program Voltage	Vpp		20.5	21	21.5	٧
Program Current	lpp	V _{PP} = 21V, CE = V _{IV}	-		30	mA
Input Leakage Current	ILI	V _{in} =5.25V/0.4V	_		10	μΑ
Input "Low" Voltage	V _{IL}		-0.1	-	0.8	٧
Input "High" Voltage	V _{IH}		2.2		V _{CC} +1.0	V
Output "Low" Voltage	V _{OL}	I _{OL} + 1.6mA	-	 	0.45	V
Output "High" Voltage	V _{OH}	I _{OH} =-200 μA	2.4		_	٧

AC CHARACTERISTICS (V_{CC}=5V±5%, V_{PP}=21V±0.5V, V_{SS}=0V, Ta=25°C±5°C, unless otherwise noted.)

ltem	Symbol	Test Condition	min	typ	max	Unit
Address Set-up Time	tAS		2	_	-	μs
Address Hold Time	t _{AH}	-	0		-	μs
OE Set-up Time	toes		2	-		μs
OE Hold Time	toeh		2	_	-	μs
Data Set-up Time	t _{DS}		2	-	T	μs
Data Hold Time	t _{DH}		2	_		μς
Output Disable Delay Time	t _{DF}		0	-	130	ns
Data Valid from CE	t _{DV}	CE=VIL, OE=VIL	_	-	1	μς
CE Pulse Width	tpw		45	50	55	ms
OE Pulse Rise Time	tPRT		50	-	_	ns
V _{pp} Recovery Time	tvR		2	_	_	μs

(Note) top is defined when output becomes open because output level can not be refered.

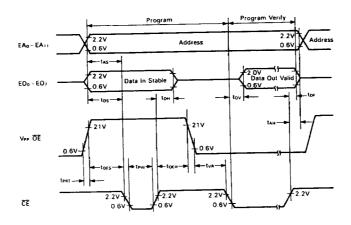


Figure 12 EPROM Programming Timing

■ FUNCTIONAL PIN DESCRIPTION

V_{CC}, V_{SS}

 V_{CC} and V_{SS} provide power to the MCU with 5V \pm 10% supply. V_{SS} pin should be tied to ground.

XTAL, EXTAL

These two pins interface a crystal (an AT-cut type). Divideby-four circuit is on chip. When 4MHz crystal is used, the system clock is 1MHz for example.

EXTAL pin may be driven with an external clock of 45 to 55% duty, and one fourth frequency of the external clock is produced in the LSI. The external clock frequency should be less

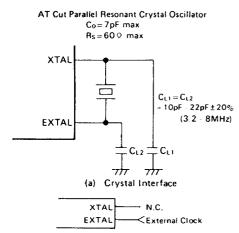


Figure 13 Connection Circuit

than four times of the maximum frequency. When using the external clock, XTAL pin should be open. Fig. 13 shows an example of connection circuit. The crystal and C_{L1} , C_{L2} should be mounted as close as possible to XTAL and EXTAL pins. Any line must not cross the line between the crystal and XTAL, EXTAL.

• STBY

This pin is used for standby mode or EPROM mode.

In standby mode, the oscillation may be stopped. To retain the contents of RAM at standby, "0" should be written into RAM enable bit (RAMW). RAME is the bit 6 of the RAM/port 5 control register at \$0014. RAM is disabled by this operation and its contents is sustained. Refer to "LOW POWER DISSIPATION MODE" for standby mode.

When this pin and Mode Program pins, MP₀ and MP₁, are "Low" level, the MCU is in EPROM mode. Refer to "PROGRAMMING THE EPROM" for details.

Reset (RES)

This pin is used to reset the MCU's internal state and provide a startup procedure. During power up, \overline{RES} pin must be held below "Low" level for more than 20 ms.

The CPU registers (accumulator, index register, stack pointer, condition code register except for interrupt mask bit), RAM and data registers of ports are not initialized during reset, so their contents are unknown in a startup procedure.

To reset the MCU during operation, \overline{RES} should be held "Low" for at least 3 system-clock cycles. At the 3rd cycle, all the address buses become "High". When \overline{RES} remains "Low", the

address buses keep "High". If RES turns "High", the MCU restart sequence is:

- (1) Latch the value of the mode program pins: MP, and MP,
- (2) Initialize each internal register (refer to Table 5).
- (3) Set the interrupt mask bit. For the CPU to recognize the maskable interrupts IRQ₁, IRQ₂ and IRQ₃, this bit should be cleared in advance.
- (4) Put the contents (=start address) of the last two addresses (\$FFFE, \$FFFF) into the program counter and start the program from this address. (Refer to Table 1).
- The MCU is unable to accept a reset input until the clock becomes normal oscillation after power on (max. 20ms). During this transient time, the MCU and I/O pins are undefined. Please be aware of this for system designing.

• Enable (E)

This pin provides a TTL-compatible clock used for bus synchronization. Its frequency is one fourth that of the internal oscillator or external clock. This pin can drive one TTL load and 90pF capacitance.

Non-Maskable Interrupt (NMI)

When the negative edge of the input signal is detected at this pin, the CPU will begin a non-maskable interrupt sequence. But the current instruction will be completed before it responds to the request. The interrupt mask bit of the condition code register doesn't affect non-maskable interrupt at all.

When the interrupt occurs, the contents of the program counter, the index register, the accumulators and the condition code register will be pushed onto the stack. Upon completion of this sequence, a vector is fetched from \$FFFC and \$FFFD, transferred their contents to the program counter and the non-maskable interrupt service routine starts. After reset, the stack pointer should be initialized on an appropriate memory area before NMI input.

● Interrupt Request (IRQ,, IRQ,)

These are level-sensitive pins which request an internal interrupt sequence. At interrupt request, the CPU will complete the current instruction before it responds to the request. If the interrupt mask in the condition code register is clear, the CPU will begin an interrupt sequence; if set, the interrupt request will be ignored. When the sequence starts, the contents of the program counter, the index register, the accumulators and the condition code register will be pushed onto the stack, then the interrupt mask bit will be set and inhibits all maskable interrupt. Finally, a vector is fetched from an address depicted in Table 1 and transferred to the program counter, and instruction execution is resumed.

The external interrupt pins, $\overline{IRQ_1}$ and $\overline{IRQ_2}$ are also used for port pins P_{50} and P_{51} , so it is controlled by Bit 0 and 1 of the RAM/port 5 control register at \$0014. Refer to "RAM/PORT 5 CONTROL REGISTER" for details.

One of the internal interrupts, ICl, OCl, TOI, CMI or SIO can generate an internal interrupt (IRQ_a). IRQ_a function is just the same as $\overline{IRQ_i}$ or $\overline{IRQ_2}$ except the vector address. Fig. 14 shows the block diagram of the interrupt circuit.

● Mode Program (MP_o, MP₁)

These two pins decide the operation mode. Refer to "MODE SELECTION" for more details.

Table 1 Interrupt Vector Memory Map

	Vec	tor	Interrupt
Priority	MSB	LSB	menapt
Highest	FFFE	FFFF	RES
•	FFEE	FFEF	TRAP
	FFFC	FFFD	NMI
	FFFA	FFFB	SWI (Software Interrupt)
	FFF8	FFF9	ĪRQ,
	FFF6	FFF7	ICI (Timer 1 Input Capture)
	FFF4	FFF5	OCI (Timer 1 Output Compare 1, 2)
	FFF2	FFF3	TOI (Timer 1 Overflow)
	FFEC	FFED	CMI (Timer 2 Counter Match)
	FFEA	FFEB	IRQ ₂
† Lowest	FFF0	FFF1	SIO (RDRF+ORFE+TDRE)

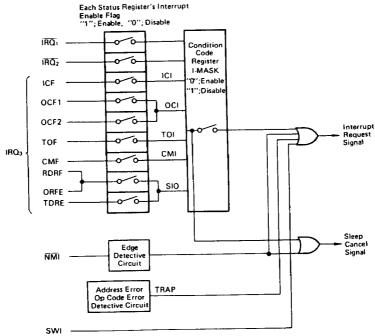


Figure 14 Interrupt Circuit Block Diagram

The following signal descriptions are applied only for expanded mode.

◆ Read/Write (R/W; P₇₂)

This signal, usually in read state ("High"), shows whether the MCU is in read ("High") or write ("Low") state. This can drive one TTL load and 30pF capacitance.

• RD, WR (Pzg, Pzz)

These outputs will turn "Low" when the CPU read/write operation is completed. This enables the CPU easy to access the peripheral LSI with RD and WR input pins. These pins can drive one TTL load and 30pF capacitance.

● Load Instruction Register (LIR; P73)

This is output for the instruction opecode on data bus (active low). This pin can drive one TTL load and 30pF capacitance.

Memory Ready (MR; P₅₂)

This input is used to stretch the system clock's "High" period in order to access low-speed memories. During this signal being in "High", the system clock operates in normal sequence. But in "Low", the "High" period of the system clock will be stretched in integral multiples of the cycle time. This allows the CPU to interface with low-speed memories (See Fig. 2). Up to $9\mu s$ can be stretched.

During internal address access or nonvalid memory access, MR is prohibited internally to prevent decrease of operation speed. Even in the halt state, MR can also stretch "High" period of system clock to allow peripheral devices to access low-speed memories. As this pin is used also for P₃₂, an enable bit is provided at bit 2 of the RAM/port 5 control register at \$0014. Refer to "RAM/PORT 5 CONTROL REGISTER" for more details.

◆ Halt (HALT; P₅₃)

This input is used to stop instruction execution or to release buses free. When this signal turns "Low", the CPU will be in the halt state after completing the current instruction. During the halt state, BA (P₂) is in "High", and an address bus, data bus, RD, WR and R/W are high impedance. When an interrupt is requested in the halt state, the CPU responds to the interrupt request after the halt is cancelled. When halted during the sleep state, the CPU keeps the sleep state, and BA is "High" and the buses are high impedance. Then the CPU returns to the previous sleep state when the HALT goes "High".

(Note) When the <u>CPU</u> is interrupt wait state in WAI instruction execution, HALT should be held "High". If HALT turns "Low", the CPU may malfunction after releasing the halt state.

Bus Available (BA; P₁₄)

This output is normally "Low" but "High" when the CPU accepts HALT and releases the buses. The HD6800 and HD6802 make BA "High" and release the buses at WAI execution, while the HD63701X0 doesn't make BA "High" under the same condition.

The following pin functions are applied only in EPROM mode. Refer to "PROGRAMMING THE EPROM" for details of EPROM mode.

● Chip Enable (CE; P_{5.7})

This pin is input for programming and verifying the EPROM. When this pin is "Low" level, EPROM will be enable.

The EPROM can not be programmed or verified in "High" level.

Program Voltage/Output Enable (V_{PP}/OE)

This pin is used for program voltage and data output control in verification.

Data from Port 3 (EO₀ to EO₇) can be programmed into the EPROM when applying $21V\pm0.5V$ to V_{pp} and holding \overline{CE} in "Low" level. The EPROM address is provided to Port 1 and Port 4 (EA₀ to EA₁). In verification, the EPROM data is output from Port 3 (EO₀ to EO₇) when this pin is "Low" level. In "High" level, Port 3 will be high-impedance. In MCU mode, this pin should be connected to V_{SS} .

■ PORT

The HD63701X0 has six 8-bit ports and a 5-bit port. Table 2 gives the address of ports and the data direction register and Fig. 15 the block diagrams of each port.

Table 2 Port and Data Direction Register Address

Port	Port Address	Data Direction Register
Port 1	\$0002	_
Port 2	\$0003	\$0001
Port 3	\$0006	\$0004
Port 4	\$0007	_
Port 5	\$0015	_
Port 6	\$0017	\$0016
Port 7	\$0018	

Port 1

In MCU mode, port 1 is used for an 8-bit output port. In mode 3, port 1 is high impedance during reset, and keeps the state even after reset is released. When the CPU writes on the port 1 data register, the written data will appear at Port 1. Once port 1 gets in the output state, it operates as an output till reset. The CPU can read the Port 1 data register for the bit manipulation instruction.

In mode 1 and 2, port 1 is used for lower address buses. This port can drive one TTL load and 90pF capacitance.

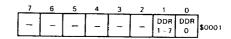
In EPROM mode, port 1 is lower address bus (EA, to EA,) for the EPROM.

Port 2

An 8-bit input/output port. Its I/O state depends on the data direction register (DDR) of port 2 which provides two bits; bit 0 decides the I/O direction of P_{20} and bit 1 the I/O direction of P_{21} to P_{27} ("0" for input, "1" for output).

Port 2 is also used for the timers and the SCI. When used for the timers and the SCI, P_{21} to P_{27} are decided I/O regardless of the DDR (except for P_{20}).

Port 2 Data Direction Register

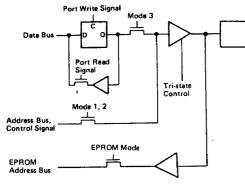


The DDR of port 2 is cleared at reset and port 2 is configured as an input. This port can drive one TTL and 30pF. In addition, it is capable of sinking ImA current at Vout=1.5V to drive directly the base of Darlington transistors.

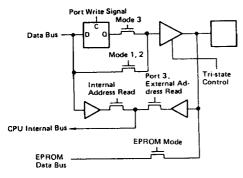
● Port 3

An 8-bit I/O port, I/O state depends on the DDR of Port 3 which has only one bit ("0" for input and "1" for output). It is cleared at reset. In mode 1 and 2, port 3 is used for data bus. This port can drive one TTL load and 90pF capacitance.

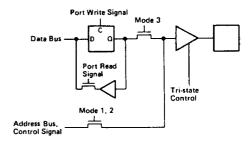
Port 3 is used for data bus (EO, to EO,) of EPROM in



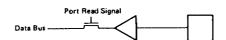
Port 1, Port 4 (Bit 0 to 3)



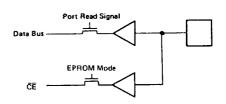
Port 3



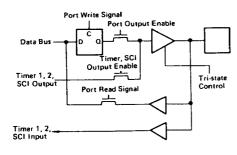
Port 4 (Bit 4 to 7), Port 7



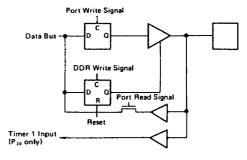
Port 5



Port 5 (Bit 7)



Port 2



Port 6, Port 2 (Bit 0)

Figure 15 Port Block Diagram

EPROM mode. In this case, I/O state of Port 3 is selected by \overline{OE} but not the DDR.

Port 3 Data Direction Register

_ 7	6	5	4	3	2	1	0	
_	_	-	-	_	-	-	Port3 DDR	\$0004

Port 4

In MCU mode, port 4 is used for an 8-bit output port like Port 1. In mode 1 and 2, it is used for upper address bus.

In EPROM mode, P_{40} to P_{43} are used for upper address bus (EA_B to EA₁₁) of EPROM.

Port 5

An 8-bit input port. The lower 4 bits are used for interrupt, MR, HALT, and P_{ca} is \overline{CE} for the EPROM control.

a Dort 6

An 8-bit I/O port. This port is programmable as either input or output under software control of the corresponding the DDR ("0" for input, "1" for output). This port can drive one TTL load and 30pF. The DDR of port 6 is cleared at reset. In addition, it is capable to sinking 1mA current at Vout=1.5V to drive directly the base of Darlington transistors.

Port 7

A 5-bit output port. In mode 3, port 7 is high impedance during reset and keeps the state even after reset is released. When the CPU writes on the port 7 data register, the written data will appear at Port 7. Once port 7 gets in the output state, it operates as an output till reset. The CPU can read the data register for the bit manipulation instruction. In this case b_7 to b_6 are "1".

In mode 1 and 2, port 7 is used for control signals (RD, WR, R/W, LIR and BA). This port can drive one TTL load and 30pF.

■ RAM/PORT 5 CONTROL REGISTER

The control register located at \$0014 controls on-chip RAM and port 5.

RAM/Port 5 Control Register

7	6	5	4	3	2	1	0	_
STBY PWR	RAME	-	_	HLTE	MRE	IRQ2 E	IRQ: E	\$0014

Bit O, Bit 1 IRQ, IRQ, Enable Bit (IRQ,E, IRQ,E)

When using P_{so} and P_{si} for interrupt pins, write "1" in these bits. When "0", the CPU doesn't accept an external interrupt or a sleep cancellation by the external interrupt. These bits are cleared at reset.

Bit 2 Memory Ready Enable Bit (MRE)

When using P_{s2} for an input for Memory Ready signal, write "1" in this bit. When "0", the memory ready function is prohibited and P_{s2} is for port. In mode 3, the memory ready function is prohibited regardless of the value of this bit. This bit is set at reset.

Bit 3 Halt Enable Bit (HLTE)

When using P_{63} for an input for Halt signal, write "1" in this bit. When "0", the halt function is prohibited. In mode 3, the

halt function is prohibited regardless of the value of this bit. This bit is set at reset.

(Note) When using P₅₂ and P₅₃ for port in mode 1 and 2, MRE and MLTE must be cleared after reset.

Bit 4. Bit 5 Not Used.

Bit 6 RAM Enable (RAME)

The RAM is controlled by this bit. It is set at reset and the RAM is enabled. This bit is programmable by software. When the RAM is disabled (=logic "0"), the CPU can access an external memory. This bit should be cleared at the beginning of standby mode to protect the RAM data.

Bit 7 Standby Power Bit (STBY PWR)

This bit is cleared whenever V_{CC} decreases below V_{RAM} (min). This is a read/write status bit by software. If this bit is set before standby mode, it indicates that V_{CC} is applied and the RAM is valid.

■ MODE SELECTION

The HD63701X0 provides two fundamental modes, MCU mode and EPROM mode. MCU mode is grouped into three; two expanded modes (mode 1, mode 2) and a single chip mode (mode 3).

These operating modes are selectable by mode program pins, MP_0 and MP_1 , and standby pin, \overline{STBY} as shown in Table 3.

• Mode 1 (Expanded Mode)

In this mode, Port 3 is data bus, Port 1 is lower address bus and Port 4 is upper address bus to interface with the HMCS6800 buses. Port 7 is used for control signal such as R/W. In mode 1, the EPROM is disable and external address space are expandable up to 65k bytes (refer to Fig. 16).

Mode 2 (Expanded Mode)

This mode is also expanded mode. But in mode 2, address space is expandable up to 61k bytes and the EPROM is enable (refer to Fig. 17).

• Mode 3 (Single-chip Mode)

In this mode, all ports are available (refer to Fig. 18).

EPROM Mode

In this mode, the EPROM can be programmed. Refer to "PROGRAMMING THE EPROM" for details.

Mode and Ports

Table 4 shows the MCU signals in each mode.

Table 3 Mode Selection

Mode	ļ	MPı	MPo	STBY	EPROM	RAM	Interrupt Vector	Operation Mode
	1	"L"	"H"	*	E	(Note 1)	E	Expanded Mode
MCU Mode	2	"H"	"L"	*	1	(Note 1)	ı	Expanded Mode
	3	"H"	"H"	*	1	1	1	Single-chip Mode
EPROM Mod	le	"L"	"L"	"L"	1	•	•	EPROM Programming Mode

"L"=Logic "0", "H"=Logic "1", I; Internal, E; External, *; Don't care (Note 1) The RAM address area will be external by clearing RAME bit at \$0014.

Table 4 MCU Signals in Each Mode

Mode		MCU Mode	EPROM Mode	
Port	Mode 1	Mode 2	Mode 3	Er Now Wode
Port 1	Address Bus (Ao ~ A7)	Address Bus (A o ~ A7)	Output Port	Address Bus (EAo ~ EA7)
Port 2	I/O Port	I/O Port	I/O Port	No use (Note 3)
Port 3	Data Bus (Do ~D7)	Data Bus (Do ~ D7)	I/O Port	Data Bus (EOo ~ EO ₇)
Port 4	Address Bus (As ~ Ais)	Address Bus (As ~ A15)	Output Port	Address Bus (EAs ~EA11) (Note 1)
Port 5	Input Port	Input Port	Input Port	CE (P ₅₇) (Nate 2)
Port 6	I/O Port	I/O Port	I/O Port	No use (Note 3)
Port 7	RD, WR, R/W, LIR, BA	RD, WR, R/W, LIR, BA	Output Port	No use (Note 3)

(Note 1) Use only 4 pins P40 to P43. P44 to P47 are not used.

(Note 2) 7 pins Pso to Pse are not used.

(Note 3) Unused ports should be connected to VSS.

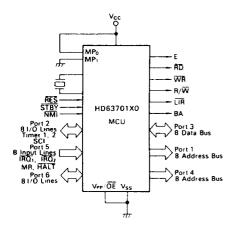


Figure 16 MCU Mode; Mode 1

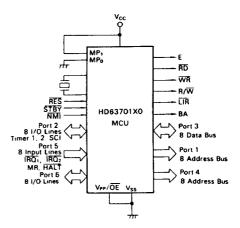


Figure 17 MCU Mode; Mode 2

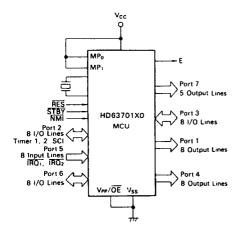


Figure 18 MCU Mode; Mode 3

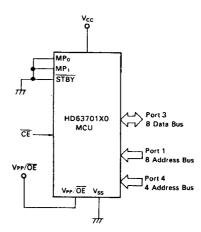


Figure 19 EPROM Mode

■ MEMORY MAP

The MCU has ability to access a 65k byte memory space depending on the operating mode. A memory map for each operat-

ing mode is shown in Fig. 20. The first 32 locations of each map are reserved for the MCU's internal register area, as shown in Table 5.

Table 5 Internal Register

Address	Registers	R/W***	Initialize at RESET
00	-		
01	Port 2 Data Direction Register	w	\$FC
02*	Port 1	R/W	Undefined
03	Port 2	R/W	Undefined
04*	Port 3 Data Direction Register	W	\$FE
05	-	_	
06*	Port 3	R/W	Undefined
07*	Port 4	R/W	Undefined
08	Timer Control/Status Register 1	R/W	\$00
09	Free Running Counter ("High")	R/W	\$00
0A	Free Running Counter ("Low")	R/W	\$00
OB OB	Output Compare Register 1 ("High")	R/W	\$FF
OC	Output Compare Register 1 ("Low")	R/W	\$FF
0D	Input Capture Register ("High")	R	\$00
0E	Input Capture Register ("Low")	R	\$00
0F	Timer Control/Status Register 2	R/W	\$10
10	Rate, Mode Control Register	R/W	\$00
11	Tx/Rx Control Status Register	R/W	\$20
12	Receive Data Register	R	\$00
13	Transmit Data Register	w	\$00
14	RAM/Port 5 Control Register	R/W	\$7C or \$FC
15	Port 5	R	
16	Port 6 Data Direction Register	W	\$00
17	Port 6	R/W	Undefined
18*	Port 7	R/W	Undefined
19	Output Compare Register 2 ("High")	R/W	\$FF
1A	Output Compare Register 2 ("Low")	R/W	\$FF
1B	Timer Control/Status Register 3	R/W	\$20
1C	Time Constant Register	w	\$FF
1D	Timer 2 Up Counter	R/W	\$00
1E			-
1F**	Test Register	-	-

^{*} External Address in Mode 1, 2.

^{**} Test Register. Do not access to this register.

^{**} R : Read Only Register
W : Write Only Register
R/W: Read/Write Register

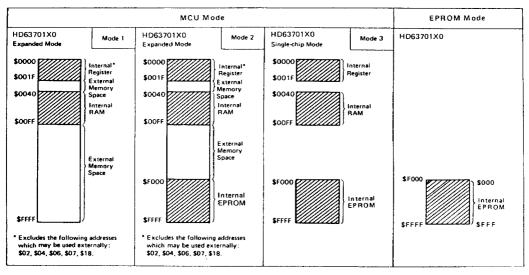


Figure 20 HD63701X0 Memory Map

■ PROGRAMMING THE EPROM

The HD63701X0 does not operate as the MCU in EPROM mode, which allows to be programmable as equivalent EPROM 2732A type. When three pins, MP₀, MP₁ and \overline{STBY} should be held low, the MCU will be in EPROM mode as shown in Table 3. In this mode, P₃₀ to P₃₇ are used for data bus, P₁₀ to P₁₇ and P₄₀ to P₄₃ for address bus, and P₆₇ for \overline{CE} input. (Refer to Fig. 19.).

• Programming/Verification

When \overline{CE} pin is held low after the program voltage (V_{PP}) is applied to V_{PP}/\overline{OE} pin, the data byte can be applied to Port 3. When V_{PP}/\overline{OE} pin and \overline{CE} pin are held low after programming, the programmed data is output from Port 3 and user can verify the data. I/O timing of these signals are referred to Fig. 12.

When CE pin is returned to high, Port 3 will be tri-state and EPROM programming/verification will be inhibited.

Table 6 shows the condition of the each pin is EPROM mode. Unused pins should be connected to GND in EPROM mode.

Erasure

Erasure of EPROM begins to occur when the LSI is exposed to ultraviolet light (wavelength, 2537 Å, an intensity of at least: 1.5W.sec/cm). Exposing the LSI to an ultraviolet lamp of 1,200 µW/cm² rating for 20 to 30 minutes, at a distance of about 1 inch, should be sufficient.

(Note) If the glass window is stained, erasure time will be extended. Remove stains from the window with a solvent which has no influence on the package like alcohol. Don't rub the window hard but wipe out softly.

■ TIMER 1

The HD63701X0 has a 16-bit programmable timer which can be used to perform input waveform measurements while generating two independent output waveforms. The pulse width can vary from several microseconds to many seconds.

Timer 1 is configurated as follows (refer to Fig. 22).

			Table 6 Pin	Condit	ION IN EPROM I	node		
Pin	Vcc	V _{SS}	V _{PP} /OE	CE	P30 to P37	P ₁₀ to P ₁₇ P ₄₀ to P ₄₃	MPo, MP1, STBY	Other pins
No.	33	1	42	24	51 to 58	43 to 50 38 to 41	4, 5, 7	
Programming	+5	GND	Vpp	"L"	Data input	Address input	"L"	GND
Verification	+5	GND	"L"	"L"	Data output	Address input	"L"	GND
Inhibition of programming/verification	+5	GND	Don't care	"H"	High impedance	Don't care	"L"	GND

Table 6 Pin Condition in EPROM mod

[&]quot;H"; VIH level, "L": VIL level

- · Control/Status Register 1 (8 bit)
- Control/Status Register 2 (7 bit)
- · Free Running Counter (16 bit)
- · Output Compare Register 1 (16 bit)
- · Output Compare Register 2 (16 bit)
- · Input Capture Register (16 bit)

• Free-Running Counter (FRC) (\$0009 : 000A)

The key timer element is a 16-bit Free-Running Counter which is incremented by system clock (E). The counter value is readable by software without affecting the FRC. It is cleared by reset

A write to the high byte of the FRC (\$09) will preset the high and low byte of the FRC to \$FFF8. A continuous write to the high and low byte FRC, however, will set them to the write data.

The FRC write timing will be as follows when double store instructions (STD, STX etc.) execute.

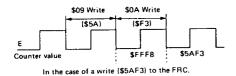


Figure 21 Counter Write Timing

Output Compare Register (OCR) (\$000B, \$000C; OCR1) (\$0019, \$001A; OCR2)

The Output Compare Register is a 16-bit read/write register used to control an output waveform. It is always compared with the FRC on each E-cycle.

When a match is found, Output Compare Flag (OCF) in the Timer Control/Status Register (TCSR) is set. If an output enable bit (OE) in the TCSR2 is "1", an output level bit (OLVL) in the TCSR will appear at Port 21 (Tout 1) or Port 25 (Tout 2).

The OCR and OLVL can then be changed for the next compare. The OCR is set to \$FFFF at reset. The compare function is inhibited for a cycle after a write to the OCR or to the high byte of the FRC. This is to set the 16-bit value valid in the register for compare. In addition, it is because \$FFF8 is set at the next cycle of a write to the high byte of the FRC.

 For a write to the FRC or the OCR, 2-byte transfer instruction (such as STX etc.) should be used.

• Input Capture Register (ICR) (\$000D : 000E)

The Input Capture Register is a 16-bit read only register used to store the FRC when an external input transition occures defined by input edge bit (IEDG) in the TCSR1.

In order to input the external signal to the edge detective circuit, Port 20 should be configured as an input. When an input capture occures at the next cycle of a read the high-byte of the ICR, the input capture will delay one cycle. In order to ensure the input capture, a read to the ICR needs 2-byte transfer instruction, and the input pulse width should be at least 2 system cycles. This register is cleared (\$0000) at reset.

• Timer Control/Status Register 1 (TCSR1) (\$0008)

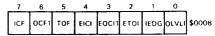
The Timer Control/Status Register 1 is an 8-bit register of which all bits are readable while the lower 5 bits can be written. The upper 3 bits indicate the following timer's status.

Bit 5 The FCR has overflowed. (TOF).

- Bit 6 A match has been found between the FCR and the OCR
- Bit 7 A level transition of the timer input has been detected

The followings are each bit descriptions.

Timer Control/Status Register 1



Bit 0 OLVL1 Output Level 1

When a match is found between the FCR and the OCR1, OLVL1 will appear at Port 21 if OE1, bit 0 of the TCSR2, is set.

Bit 1 IEDG Input Edge

This bit controls which level transition will trigger the FCR transfer to the ICR. For this function, the DDR corresponding to Port 20 should be cleared. IEDG=0, transferred on a negative edge

IEDG=1, transferred on a positive edge

Bit 2 ETOI Enable Timer Overflow Interrupt

When this bit is set, an internal interrupt (IRQ₃) is enabled for TOI. When cleared, the interrupt is inhibited.

Bit 3 EOCi1 Enable Output Compare Interrupt 1

When this bit is set, an internal interrupt (IRQ_3) is enabled for OCII. When cleared, the interrupt is inhibited.

Bit 4 EICI Enable Input Capture Interrupt

When this bit is set, an internal interrupt (IRQ3) is enabled for ICl. When cleared, the interrupt is inhibited.

Bit 5 TOF Timer Overflow Flag

This read only bit is set when the FCR contains all 1's. It is cleared by reading the TCSR1 followed by the FCR's high byte (\$0009).

3it 6 OCF1 Output Compare Flag 1

This read only bit is set when a match is found between the OCR1 and the FRC. It is cleared by writing to the OCR1 (\$000B or \$000C) followed by reading the TCSR1 or TCSR2.

Bit 7 ICF Input Capture Flag

This read only bit is set to indicate a level transition defined by IEDG. It is cleared by reading the high byte (\$000D) of the ICR followed by the TCSR1 or TCSR2.

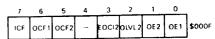
• Timer Control/Status Register 2 (TCSR2) (\$000F)

The Timer Control/Status Register 2 is a 7-bit register. All bits are readable while the lower 4 bits can be written. The upper 3 bits indicate the following timer's status.

- Bit 5 A match has been found between the FRC and the OCR2 (OCF2).
- Bit 6 The same flag as the OCF1 of the TCSR1.
- Bit 7 The same flag as the ICF of the TCSR1.

The followings are each bit descriptions.

Timer Control/Status Register 2



Bit O OE1 Output Enable 1

If this bit is set, the OLVL1 will appear at Port 21 when a match is found between the FCR and the OCR1. When it is cleared, Port 21 will be 1/0 port. When set, it will be an output of OLVL1 automatically.

Bit 1 OE2 Output Enable 2

If this bit is set, the OLVL2 will appear at Port 25 when a match between the FCR and the OCR2. When this bit is cleared, Port 25 will be I/O port. When set, it will be an output of OLVL2 automatically.

Bit 2 OLVL2 Output Level 2

OLVL2 is transferred to Port 25 when a match is found between the FCR and the OCR2. If OE2, bit 5 of the TCSR2, is set, OLVL2 will appear at Port 25.

Bit 3 EOCI2 Enable Output Compare Interrupt 2

When this bit is set, an internal interrupt (IRQ_π) is enabled for OC12. When cleared, the interrupt is inhibited.

Bit 4 Not Used

Bit 5 OCF2 Output Compare Flag 2

This read-only bit is set when a match is found between the FCR and the OCR2. It is cleared by writing to the OCR2 (\$0019 or \$001A) followed by reading the TCSR2

Bit 6 OCF1 Output Compare Flag 1

Bit 7 ICF Input Capture Flag

OCF1 and ICF addresses are partially decoded. CPU read of the TCSR1/TCSR2 makes it possible to read OCF1 and ICF into bit 6 and bit 7.

Both the TCSR1 and TCSR2 will be cleared by reset.

(Note) If OE1 or OE2 is set before the first output compare match is found after reset, Port 21 and Port 25 will output "0" respectively.

(Note) Because the set condition of ICF precedes its reset condition, ICF is not cleared when the set condition and the reset condition occur simultaneously. The same phenomenon applies to OCF1, OCF2 or TOF respectively.

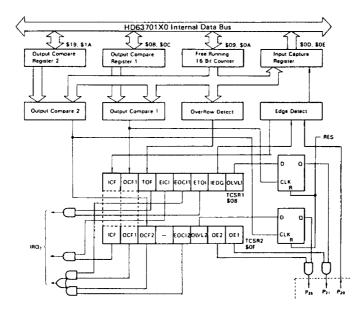


Figure 22 Timer 1 Block Diagram

■ TIMER 2

In addition to the timer 1, the HD63701X0 provides an 8-bit reloadable timer, which is capable of counting the external event. This timer 2 contains a timer output, so the MCU can generate three independent waveforms. (Refer to Fig. 23.)

The timer 2 is configured as follows: Control/Status Register 3 (7 bit) 8-bit Up Counter

Time Constant Register (8 bit)

• Timer 2 Up Counter (T2CNT) (\$001D)

This is an 8-bit up counter which is incremented by the clock controlled by CKS0 and CKS1 of the TCSR3. The T2CNT is always readable without affecting itself. In addition, any value can be written to the T2CNT by software even during counting.

The counter is cleared when a match is found between the T2CNT and the TCONR or by reset.

A write to the T2CNT at the clear cycle does not reset it but

put the data to it.

• Time Constant Register (TCONR) (\$001C)

The Timer Constant Register is an 8-bit write only register. It is always compared with the T2CNT.

When a match has been found, counter match flag (CMF) of the Timer Control/Status Register 3 (TCSR3) is set and the value selected by TOS0 and TOS1 of the TCSR3 will appear at Port 26. When CMF is set, the FCR will be cleared simultaneously and then a counting starts from \$00. This enables regular interrupts and waveform outputs without any software support. The TCONR is set to "\$FF" by reset.

• Timer Control/Status Register 3 (TCSR3) (\$001B)

The Timer Control/Status Register 3 is a 7-bit register. All bits are readable while 6 bits except for CMF can be written.

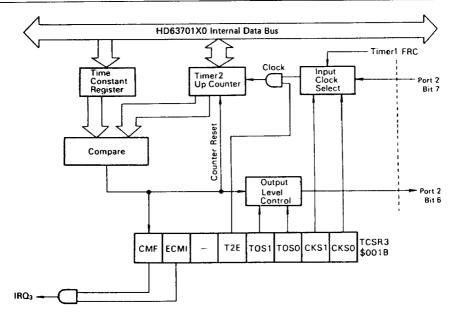


Figure 23 Timer 2 Block Diagram

The followings are each bit descriptions.

Timer Control/Status Register 3 7 6 5 4 3 2 1 0 CMF ECMI — T2E TOS1 T0S0 CKS1 CKS0 \$0018

Bit 0 CKS0 Input Clock Select 0 Bit 1 CKS1 Input Clock Select 1

An input clock to the T2CNT is selected by these bits as shown in Table 7. When an external clock is selected, Port 27 will be an input automatically. The positive edge of the external clock increments the T2CNT. The maximum external clock is half of the system clock frequency.

Table 7 Input Clock Select

CKS1	CKS0	Input Clock to the Counter
0	0	E clock
0	1	E clock/8*
1	0	E clock/128*
1	1	External clock

These clocks come from the FRC of the timer 1. If one of these clocks is selected as an input clock to the up counter, a write to the FRC of the timer 1 should be inhibited.

Bit 2 TOSO Timer Output Select 0 Bit 3 TOS1 Timer Output Select 1

When a match is found between the T2CNT and the TCONR, timer 2 output selected by these bits shown in Table 8 will appear at Port 26. When both TOS0 and TOS1 are cleared, Port 26 will be an 1/O port.

Table 8 Timer 2 Output Select

TOS1	TOS0	Timer Output
0	0	Timer Output Inhibited
0	1	Toggle Output*
1	0	Output "0"
1	1	Output "1"

When a match is found between the T2CNT and the TCONR, timer 2 output level is reversed. This leads to production of a square wave with 50% duty to the external without any software support.

Bit 4 T2E Timer 2 Enable Bit

When this bit is cleared, the T2CNT will stop. When set, a clock selected by CKS1 and CKS0 (Table 7) provides to the T2CNT.

(Note) P₂₆ is "0" when T2E is cleared and P₂₈ is configured as an output by TOSI or TOSO. It also is "0" when T2E is set and P₂₆ is configured as an output before the first counter match.

Bit 5 Not Used

Bit 6 ECMI Enable Counter Match Interrupt

When this bit is set, an internal interrupt (IRQ_a) is enabled for CMI. When cleared, the interrupt is inhibited. Bit 7 CMF Counter Match Flag

This read only bit is set when a match is found between the T2CNT and the TCONR. It is cleared by writ-

ing "0". (It cannot be written "1" by software). Each bit of the TCSR3 is cleared by reset.

■ SERIAL COMMUNICATION INTERFACE (SCI)

The HD63701X0 SCI provides two operation modes; one is an asynchronous mode by the NRZ format and the other is a clocked synchronous mode to transfer data synchronizing with the serial clock.

The serial interface is configured as follows:

- Transmit/Receive Control and Status Register (TRCSR)
- · Rate/Mode Control Register (RMCR)
- · Receive Data Register (RDR)
- · Receive Data Shift Register (RDSR)
- · Transmit Data Register (TDR)
- · Transmit Data Shift Register (TDSR)

The SCI is initialized by software. The procedure is usually as follows:

- Write a operation mode into each corresponding control bit of the RMCR.
- Write a operation mode into each corresponding control bit of the TRCSR.

When setting the baud rate and operation mode, TE and RE should be "0". When TE and RE is set again, more than 1 bit cycle of the current baud rate is necessary. If set in less than 1 bit cycle, the SCI cannot be initialized occasionally.

Asynchronous Mode

An asynchronous mode contains the following two data formats:

- 1 Start Bit + 8 Bit Data + 1 Stop Bit; 8 Bit Data Format 1 Start Bit + 9 Bit Data + 1 Stop Bit; 9 Bit Data Format
- In 9 Bit Data Format, if the 9th bit is "1", the format of
 - 1 Start Bit + 8 Bit Data + 2 Stop Bit

The SCI is initialized by writing desirable control bytes to the RMCR and then to the TRCSR.

The transmit operation is enabled by TE in the TRCSR. When TE is set, the output of the TDSR is connected to P₂₄ which will be configured as an output regardless of the DDR, and then the serial output is initiated by transmitting to a 10-bit preamble of "1" in the 8 Bit Data Format or an 11-bit preamble of "1" in the 9 Bit Data Format. Following the preamble, the internal synchronization is established and the transmitter section is ready for operation.

At this point one of two situation exist:

- If the TDR is empty (TDRE=1), a continuous string of ones will be sent indicating an idle line.
- If a byte has been written to the TDR (TDRE=0), it is transferred to the TDSR, TDRE will be set and transmission will begin.

During the transfer itself, the start bit (0) is first transmitted. Then the 8 data bits or the 9 data bits (beginning with bit 0) followed by the stop bit (1) are transmitted. When the TDR has been emptied, TDRE is set.

If the MCU fails to respond to the flag within the proper time, (TDRE is still set when the next normal transfer from the TDR to the TDSR should occure) then a "1" will be sent (instead of a "0") at start bit time, followed by more 1's until more data is supplied to the TDR. No 0's will be sent while TDRE remains as "1".

The receive operation is enabled by RE which configures P₂₃. The receive operation is controlled by the contents of the TRCSR and the RMCR. The receiver bit interval is divided into 8 sub-intervals for internal synchronization. The received bit stream is synchronized by the first "0" (space) encountered. The approximate center of each bit time is strobed during the next 10 bits.

If the tenth bit is not a "1" (stop bit), a framing error is assumed and ORFE is set. If the tenth bit is a "1", the data is transferred to the RDR and interrupt flag RDRF is set. If RDRF is still set at the next tenth bit time, ORFE will be set, indicating an over-run has occurred. When the CPU responds to either flag

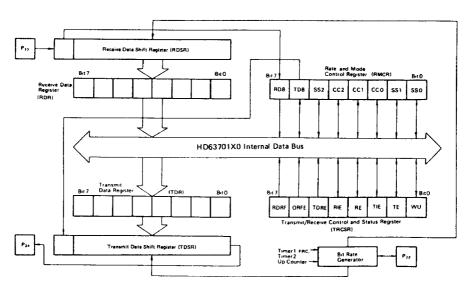


Figure 24 Serial Communication Interface Block Diagram

(RDRF or ORFE) by reading the TRCSR followed by reading the RDR, RDRF (or ORFE) will be cleared.

(Note) Clock Source in Asynchronous Mode

When using an internal clock for the SCI, the following requirements are applicable:

- · Set CC1 and CC0 to "1" and "0" respectively.
- A clock is generated regardless of the value of TE, RE.
- . The maximum clock rate is E+16.
- · The output clock is the same as the bit rate.

When using an external clock for the SCI, the following requirements are applicable:

- Set CC1 and CC0 in the RMCR to "1" and "1" respectively.
- The external clock should be set 16 times the desired baud rate.
- the maximum clock frequency is the same as the system clock.

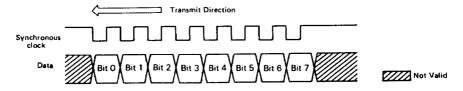
Clocked Synchronous Mode

In the clocked synchronous mode, the transmit operation is synchronized with the clock pulse. In the clocked synchronous mode an SCI clock I/O pin is only P_{22} , so the receive and transmit operation cannot be simultaneously enabled. Therefore, TE and RE should not be set simultaneously. Fig. 25 gives a synchronous clock and a data format in the clocked synchronous mode.

The transmit operation is enabled by TE in the TRCSR. P_{z4} is configured as an output regardless of the value of the corresponding DDR.

Both the RMCR and TRCSR should be set in the desirable operating conditions for data transmit.

If the user wishes to provide an external clock, the data bits (beginning with bit 0) are transmitted from P_{zz} , synchronizing with 8 clock pulses supplied to P_{zz} , when TDRE is "0". TDRE is set when the TDSR is "empty". More the 9th clock pulse is ignored.



- . Transmit data is sent between the negative edge of a synchronous clock and the next negative edge.
- · Receive data is latched at the positive edge

Figure 25 Clocked Synchronous Mode Format

The receive operation is enabled by RE. P_{22} is configured as an input for the 8 bit external clock and P_{23} is configured as an input for the receive data. The operating mode of data receive is decided by the TRCSR and the RMCR.

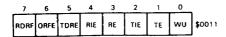
If the external clock is provided, RE should be set when P_{22} is "High". The receive data is transferred to the RDSR by this clock, and RDRF is set. More the 9th clock pulse are ignored. When RDRF is cleared by reading the RDR, the MCU starts receiving the next data.

RDRF, therefore, should be cleared with P_{22} "High". When the first byte data is received, RDRF is set. After the second byte, the receive operation is enabled by clearing RDRF.

Transmit/Receive Control and Status Register (TRCSR) (\$0.011)

The TRCSR is an 8 bit register which is readable. Bits 0 to 4 are also writable. This register is initialized to \$20 by reset. Each bit functions as follows.

Transmit/Receive Control Status Register



Bit 0 WU Wake-up

In a typical multi-processor configuration, the software protocol will usually identify the address at the beginning of the message. In order to permit uninterested MCU's to ignore the remaining message, a wake-up function is

available. By this, uninterested MCU can inhibit all further receive processing till the next message starts.

Then wake-up function is triggered by consecutive 1's with I frame length (10 bits for the 8-bit data format, or 11 bits for the 9-bit data format). The software protocol should provide the idle time between messages.

By setting this bit, the MCU stops data receive till the next message. The receive of consecutive "1" with one frame length wakes up and clears this bit and then the MCU restarts the receive operation. However, the RE flag should be set before setting this bit. In the clocked synchronous mode WU is not available, so this bit should not be set.

Bit 1 TE Transmit Enable

When this bit is set, transmit data will appear at P_{24} after one frame preamble in asynchronous mode, while in clocked synchronous mode appear immediately. This is executed regardless of the value of the corresponding DDR. When TE is cleared, the serial I/O doesn't affect P

Bit 2 TIE Transmit Interrupt Enable

When this bit is set, an internal interrupt (IRQ_3) is enabled when TDRE (bit 5) is set. When cleared, the interrupt is inhibited.

Bit 3 RE Receive Enable

When set, P_{23} is configured as an input for the receive operation regardless of the value of the DDR. When RE is cleared, the serial I/O doesn't affect P_{23} .

Bit 4 RIE Receive Interrupt Enable

When this bit is set, an internal interrupt, IRQ₃ is enabled when RDRF (bit 7) or ORFE (bit 6) is set. When cleared, the interrupt is inhibited.

Bit 5 TDRE Transmit Data Register Empty

TDRE is set when the TDR is transferred to the TDSR in the asynchronous mode, while it is set when the TDSR is "empty" in clocked synchronous mode. This bit is cleared by reading the TRCSR and writing the new transmit data to the TDR. TDRE is set by reset.

(Note) TE should be set before clearing TDRE.

Bit 6 ORFE Overrun Framing Error

ORFE is set when an overrun or a framing error is occured (during data receive only). An overrun error occurs when a new receive data is ready to be transferred to the RDR with RDRF still set. A framing error occurs when a stop bit is "0". But in clocked synchronous mode, this bit is not affected. This bit is cleared when reading the TRCSR, then the RDR, or by reset.

Bit 7 RDRF Receive Data Register Full

RDRF is set when the RDSR is transferred to the RDR. Cleared when reading the TRCSR, then the RDR, or by reset.

(Note) When a few bits are set between bit 5 to bit 7 in the TRCSR, a read of the TRCSR is sufficient for clearing those bits. It is not necessary to read the TRCSR everytime to clear each bit.

• Rate/Mode Control Register (RMCR)

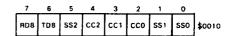
The RMCR controls the followings:

- · Baud Rate
 · Clock Source
- · Data Format
- · P₂₂ Function

In addition, if 9-bit data format is set in the asynchronous mode, the 9th bit is put in this register. All bits are readable and writable except bit 7 (read only). This register is cleared by reset.

These bits select the baud rate when using the internal clock. Table 9 lists the available bit times and baud rates. The timer 1's FRC (SS2=0) and the timer 2's up counter (SS2=1) provide

Rate/Mode Control Register



the internal clock for the SCI. When the source of the SCI internal clock is the timer 2's up counter, the desired baud rates may be selected by the TCONR shown in Table 10.

(Note) When operating the SCI with internal clock, do not write to the counter which is the source of the SCI clock.

These bits select the data format and the clock source (refer to Table 11).

 CC0, CC1 and CC2 are cleared and the MCU will be in the clocked synchronous mode (the external clock operation) by reset. Then P₂₂ is forced to be configured as an input for the clock. If using P₂₂ for an output, the DDR of port 2 should be set to "1" and CC1, CC0 must be set to "01".

Table 9 SCI Bit Times and Rates

(1) Asynchronous Mode

			XTAL	2.4576MHz	4.0MHz	4.9152MHz
SS2	SS1	sso	E	614.4kHz	1.0MHz	1 2288MHz
0	0	0	E÷16	26 ks/38400Baud	16 µs/62500Baud	13 µs/76800Baud
0	o	1	E÷128	208 µs/4800Baud	128 _{/rs} /7812.5Baud	104.2 /rs/9600Baud
0	1	0	E ÷ 1024	1.67ms/600Baud	1.024ms/976.6Baud	833.3 µs/1200Baud
0	1	1	E÷4096	6.67ms/150Baud	4 096ms/244 1Baud	3.333ms/300Baud
1		_		*	*	*

^{*}When SS2 is "1", Timer 2 provides SCI clocks. The haud rate is shown as follows with the TCONR as N.

Baud Rate =
$$\frac{f}{32 \text{ (N+1)}}$$
 $\left(\begin{array}{c} f: \text{ input clock frequency to the} \\ \text{timer 2 counter} \\ N=0\sim255 \end{array}\right)$

(2) Clocked Synchronous Mode *

_			XTAL	4.0MHz	6.0MHz	8.0MHz
SS2	SS1	sso	E	1.0MHz	1.5MHz	2.OMHz
0	0	0	E ÷ 2	2 µs/bit	1.33µs/bit	1μs/bit
0	0	1	E÷16	16 µs/bit	10.7μs/bit	8µs/bit
0	1	0	E÷128	128//s/bit	85.3μs/bit	64µs/bit
0	1	1	E÷512	512µs/bit	341 µs/bit	256μs/bit
1	_	_ \	-	* *	**	* *

^{*} Bit rates in the case of internal clock operation. In the case of external clock operation, the external clock is operatable up to DC $\sim 1/2$ system clock.

Table 10 Baud Rate and Time Constant Register Example

Baud Rate (Baud)	2.4576MHz	3.6864MHz	4.0MHz	4.9152MHz	8.0MHz
110	21*	32.	35.	43*	70°
150	127	191	207	255	51.
300	63	95	103	127	207
600	31	47	51	63	103
1200	15	23	25	31	51
2400	7	11	12	15	25
4800	3	5	-	7	12
9600	1	2		3	
19200	o	-	***	1 1	_
38400	= '	_		0	_

^{*}E/8 clock is provided to the timer 2's up counter.

^{**} The bit rate is shown as follows with the TCONR as N.

Table 11 SCI Format and Clock Source Control

CC2	CC1	CCO	Format	Mode	Clock Source	Port 2, Bit 2	Port 2, Bit 3	Port 2, Bit 4	
0	0	0	8-bit data	Clocked Synchronous	External	Input	h		
0	0	1	8-bit data	Asynchronous	Internal	Not Used**			
0	1	0	8-bit data	Asynchronous	Internal	Output*	When RE is "1", bit 3 is used for a serial input.		
0	1	1	8-bit data	Asynchronous	External	Input			
1	0	0	8-bit data	Clocked Synchronous	Internal	Output			
1	0	1	9-bit data	Asynchronous	Internal	Not Used**			
1	1	0	9-bit data	Asynchronous	Internal	Output*	When TE is "1", bit 4 is used for a serial output.		
1	1	1	9-bit data	Asynchronous	External	Input			

^{*} Clock output regardless of RE or TE in the TRCSR.

Bit 6 TD8 Transmit Data Bit 8

When selecting the 9-bit data format in the asynchronous mode, this bit is transmitted as the 9th data

Bit 7 RD8 Receive Data Bit 8

When selecting the 9-bit data format in the asynchronous mode, this bit stores the 9th bit data.

■ TIMER, SCI STATUS FLAG

Table 12 shows set and clear conditions of each status flag in the timer 1, the timer 2 and the SCI.

If the flag set and clear conditions occur at the same time, the

flag of the Timer 1 and the Timer 2 will be set, and the SCI cleared. Therefore the OCF1 and OCF2 of the Timer 1 may not be cleared correctly because set signal is generated periodically whenever the OCR matches the FRC. In order to clear these flags correctly, the match should be prohibited during the period between reading the TSCR and writing the OCR. For instance, these flags will be cleared correctly if the TCSR is read and the OCR is written continuously soon after matching the value of the OCR and the FCR.

Table 12 Timer 1, Timer 2 and SCI Status Flag

		Set Condition	Reset Condition
	ICF	FRC → ICR by edge input to P ₂₀ .	1. Read the TCSR1 or TCSR2 then ICRH, when ICF = 1 2. RES=0
Timer	OCF1	OCR1=FRC	1. Read the TCSR1 or TCSR2 then write to the OCR1H or OCR1L, when OCF1=1 2. RES=0
1 imer 1	OCF2	OCR2=FRC	1. Read the TCSR2 then write to the OCR2H or OCR2L, when OCF2=1 2. RES=0
	TOF	FRC=\$FFFF+1 cycle	1. Read the TCSR1 then FRCH, when TOF = 1 2. RES=0
Timer 2	CMF	T2CNT=TCONR	1. Write "0" to CMF, when CMF = 1 2. RES=0
	RDRF	Receive Shift Register → RDR	1. Read the TRCSR then RDR, when RDRF = 1 2. RES=0
SCI	ORFE	 Framing Error (Asynchronous Mode) Stop Bit = 0 Overrun Error (Asynchronous Mode) Receive Shift Register → RDR when RDRF=1 	Read the TRCSR then RDR, when ORFE = 1 RES = 0
	TDRE 1. Asynchronous Mode TDR → Transmit Shift Register 2. Clocked Synchronous Mode Transmit Shift Register is "empty" 3. RES=0		Read the TRCSR then write to the TDR, when TDRE=1 (Note) Clear TDRE after setting TE.

⁽Note) 1. →; transfer

^{**} Not used for the SCI.

^{2.} For example; "ICRH" means High byte of ICR.

■ LOW POWER DISSIPATION MODE

The HD63701X0 provides two low power dissipation modes; sleep and standby.

Sleep Mode

The MCU will be in the sleep mode when SLP instruction is executed. In the sleep mode, the CPU stops and the registers' contents are retained. While the peripherals such as timers, SCI etc. continue their functions. The power dissipation of the sleep-condition is one fifth that of the operating condition.

The MCU returns from this mode by an interrupt, RES or STBY; it will be reset by RES and the standby mode by STBY. When the CPU responds to an interrupt request, it cancels the sleep mode, returns to the operation mode and branches to the interrupt routine. When the CPU masks this interrupt, it cancels the sleep mode and executes the next instruction. However, for example if the timer 1 or 2 prohibits a timer interrupt, the CPU doesn't cancel the sleep mode because of no interrupt request.

This sleep mode is effective to reduce the power dissipation for a system with no need of the HD63701X0's consecutive op-

eration.

Standby Mode

In MCU mode, the HD63701X0 stops and reset with STBY "low". In this mode, the power dissipation is reduced conspicuously. All pins except for the power supply, STBY and XTAL are detached from the MCU internally and will be the high impedance state.

While the contents of RAM is retained. The MCU returns from this mode by reset. The followings are typical usage of this mode.

Save the CPU information and SP contents on RAM by NMI. Then disable the RAME bit of the RAM control register and set the STBY PWR bit to go to the standby mode. If the STBY PWR bit is still set at reset, that indicates the power is supplied to the MCU and RAM contents are retained properly. So system can restore itself by returning their pre-standby informations to the SP and the CPU. Fig. 26 depicts the timing at each pin with this example.

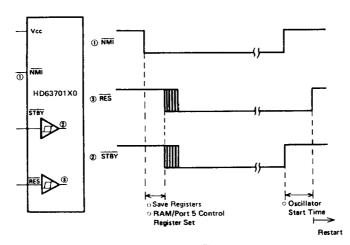


Figure 26 Standby Mode Timing

TRAP FUNCTION

The CPU generates an interrupt with the highest priority (TRAP) when fetching an undefined instruction or an instruction from non-memory space. The TRAP prevents the system-burst caused by noise or a program error.

Op Code Error

When fetching an undefined op code, the CPU saves CPU registers as well as a normal interrupt and branches to the TRAP (\$FFEE, \$FFEF). This provides the priority next to reset.

Address Error

When an instruction fetch is made excluding internal ROM, RAM and external memory area, the MCU generates an interput as well as an op code error. But on the system with no memory in its external memory area, this error processing is not applicable if an instruction fetch is made from the external non-memory area. Table 13 provides addresses where an address error occurs to each mode.

This processing is available only for an instruction fetch and is not applicable to the access of normal data read/write.

Table 13 Addresses Applicable to Address Errors

Mode	1	2	3
Address	\$0000	\$0000	\$0000

(Note) The TRAP interrupt provides a retry function differently from other interrupts. This is a program flow return to the address where the TRAP occurs when a sequence returns to a main routine from the TRAP interrupt routine by RTI. The retry can prevent the system burst caused by noise etc.

However, if another TRAP occurs, the program repeats the TRAP interrupt forever, so the consideration is necessary in programming.

■ INSTRUCTION SET

The HD63701X0 provides object code upward compatible with the HD6801 to utilize all instruction set of the HMC56800. It also reduces the execution times of key instructions for throughout improvement.

Bit manipulation instruction, change instruction of the index register and accumulator and sleep instruction are also added.

The followings are explained here.

- · CPU Programming Model (refer to Fig. 27)
- · Addressing Mode
- Accumulator and Memory Manipulation Instruction (refer to Table 14)
- · New Instruction
- Index Register and Stack Manipulation Instruction (refer to Table 15)
- · Jump and Branch Instruction (refer to Table 16)
- · Condition Code Register Manipulation
- (refer to Table 17)
- · Op Code Map (refer to Table 18)

Programming Model

Fig. 27 depicts the HD63701X0 programming model. The double accumulator D consists of accumulator A and B, so when using the accumulator D, the contents of A and B are destroyed.

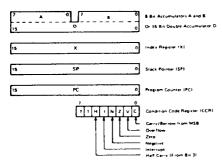


Figure 27 CPU Programming Model

CPU Addressing Mode

The HD63701X0 provides 7 addressing modes. The addressing mode is decided by an instruction type and code. Table 14 through 18 show addressing modes of each instruction with the execution times counted by the machine cycle.

When the clock frequency is 4MHz, the machine cycle time becomes microseconds directly.

Accumulator (ACCX) Addressing

Only an accumulator is addressed and the accumulator A or B is selected. This is a one-byte instruction.

Immediate Addressing

This addressing locates a data in the second byte of an instruction. However, LDS and LDX locate a data in the second and third byte exceptionally. This addressing is a 2 or 3-byte instruction.

Direct Addressing

In this addressing mode, the second byte of an instruction shows the address where a data is stored. 256 bytes (\$0 through \$255) can be addressed directly. Execution times can be reduced by storing data in this area so it is recommended to make it RAM for users' data area in configurating a system. This is a 2-byte instruction, while 3 byte with regard to AIM, OIM, EIM and TIM.

Extended Addressing

In this mode, the second byte shows the upper 8 bit of the data stored address and the third byte the lower 8 bit. This indicates the absolute address of 3 byte instruction in the memory. Indexed Addressing

The second byte of an instruction and the lower 8 bit of the index register are added in this mode. As for AIM, OIM, EIM and TIM, the third byte of an instruction and the lower 8 bits of the index register are added.

This carry is added to the upper 8 bit of the index register and the result is used for addressing the memory. The modified address is retained in the temporary address register, so the contents of the index register doesn't change. This is a 2-byte instruction except AIM, OIM, EIM and TIM (3-byte instruction). Implied Addressing

An instruction itself specifies the address. That is, the instruction addresses a stack pointer, index register etc. This is a onebyte instruction.

Relative Addressing

The second byte of an instruction and the lower 8 bits of the program counter are added. The carry or borrow is added to the upper 8 bit. So addressing from -126 to +129 byte of the current instruction is enabled. This is a 2-byte instruction.

(Note) CLI, SEI Instructions and Interrupt Operation

When accepting the IRQ at a preset timing with the help of CLI and SEI instructions, more than 2 cycles are necessary between the CLI and SEI instructions. For example, the following program (a) (b) don't accept the IRQ but (c) accepts it.

	•	
	•	
•	•	
	•	CLI
CLI	CLI	NO
SEI	NOP	NO
	SEI	SEI
	•	
	•	
•	•	
(a)	(b)	(c)

The same thing can be said to the TAP instruction instead of the CLI and SEI instructions.

Table 14 Accumulator, Memory Manipulation Instructions

							Add	ressi	ng N	Mod	es			,				С			on C ister		e
Operations	Mnemonic	IMI	ME)	DIF	1EC	т	IN	DE)	(EXI	EN	Ď	IMP	LIE	ō	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		OP	~	*	OP	~	n	OP	~	#	OP	~		OP	~	#		н	1	Z	z	v	С
Add	ADDA	88	2	2	98	3	2	AΒ	4	2	88	4	3				A + M→ A	1	٠	!	1	1	1
	ADDB	СВ	2	2	DΒ	3	2	EÐ	4	2	FB	4	3				B + M → 8	1	٠	1	1	1	1
Add Double	ADDD	C3	3	3	D3	4	2	E3	5	2	F3	5	3				A.B+M:M+1-+A.B	•	٠	1	1	1	1:
Add Accumulators	ABA			Ι.		_								18	1	ī	A + B - A	1	•	ī	1	1	1
Add With Carry	ADÇA	89	2	2	99	3	2	Α9	4	2	В9	4	3				A + M + C - A	1	٠	:	1	1	1
	ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3				B + M + C → B	1	٠	1	1	1	1
AND	ANDA	84	2	2	94	3	2	A4	4	2	84	4	3				A·M - A	•	•	1	1	R	•
	ANDB	C4	2	2	D4	3	2	€4	4	2	F4	4	3				B-M → B	•	•	1	1	R	•
Bit Test	BITA	85	2	2	95	3	2	A 5	4	2	B 5	4	3			_	A-M	•	٠	;	1	R	•
	BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3			1	B·M	•	•	1	1	R	1.
Clear	CLR	 	1	m			Г	6F	5	2	7 F	5	3				00 → M	•	•	R	S	R	R
	CLRA	T	t			\vdash			П			Γ	Г	4F	1	1	00 + A	•	•	R	S	R	R
	CLRB	1	T			Ι-	Ι		1	Г	1	1	Г	5F	ī	1	00 · B	•	•	R	S	R	R
Compare	CMPA	81	2	2	91	3	2	Α1	4	2	В1	4	3	П		Г	A - M	•	•	1	1	1	1
	СМРВ	C1	2	2	D1		2	E1	4	2	F١	4	3				B - M	•	•	1	1	1	1
Compare Accumulators	СВА	\dagger	1	T		T	İ	1-		-		Г	Г	11	1	1	A - B	•	•	ı	1	1	ŀ
Complement, 1's	COM	1	T	1				63	6	2	73	6	3		Г	T	M · M	•	•	1	1	R	S
	COMA	+	t	T	t	一	t		1		†	t	Г	43	1	Ť	A - A	•	•	1	1	R	S
	COMB	1	T	T			Ī		Г		1		Γ	53	1	ī	8 → 8	•	•	1	1	R	S
Complement, 2's	NEG	†	+	1	t	1	t	60	6	2	70	6	3		┢	T	00 - M -+ M	1.	•	1	1	Œ	7
(Negate)	NEGA	+		1		1	T		Г				Γ	40	1	ī	00 - A → A	•	•	ı	1	19) (2
	NEGB	1	1			Г	Т					Γ	Γ	50	1	1	00 - B → B	•	•	1	1	Œ) (2
Decimal Adjust, A	DAA		T	Γ	Γ		Ī							19	2	1	Converts binary add of BCD characters into BCD format	•	•	1	1	:	(3)
Decrement	DEC	1	Т	Т	Γ	Т	Т	6A	6	2	7A	6	3		Г	Г	M = 1 -+ M	•	•	1	1	(4	• ار
	DECA		Т	T			T		Τ	Г		Τ		44	1	1	A - 1 - A	•	•	1	:	(4	<u> </u>
	DECB	1		Т	П	T	Γ		Т	П	Π	Т	Γ	5A	ī	ı	B - 1 → B		•	1	1	(4	0 •
Exclusive OR	EORA	88	2	2	98	3	2	A8	4	2	88	4	3	П	Г	Т	A ⊕ M → A	•	•	1	1	F	٦.
	EORB	C8	2	2	08	3	12	E8	4	2	F8	4	3		Т	Т	8 • M → B	•	1.	1	1	F	Ţ
Increment	INC		Τ	1	T		1	6C	6	2	7C	6	3		Т	T	M+1 -M	•	•	Ţi	T	(<u>ه</u>
	INCA	_	†	1	t	T	1	1	1	ţ	1	T	T	4C	1	1	A + 1 + A	•	•	1	1	10	5 0
	INCB		+	十	1	t	t	1-	†	T	1	1	T	5C	1	1	B + 1 → B	1.	1	1	1	C	5
Load	LDAA	86	2	2	96	3	2	Α6	4	2	86	4	3	Ī	T	T	M → A	1•	•	1	1	F	ग
Accumulator	LDAB	C6	_		06	3	2	€6	4	2	F6	4	3	T	T	Т	M B	•		1	:	F	ग
Load Double Accumulator	LOD	cc	1	+	DC	+	2	ΕC	5	2	FC	5	3				M + 1 -+ B, M -+ A	•	•	1	1	F	١,
Multiply Unsigned	MUL	1	1	Τ	Π	1	T			Τ	T	T	Γ	30	7	1	A x B - A : B	ŀ	ŀ	Ţ	•	•	• 0
OR, Inclusive	DRAA	84	2	2	9A	3	2	A/	4	2	ВА	4	73	1		Т	A + M - A	•	T	1	1		۹ آ
	ORAB	CA	2	2	0.4	1 3	12	EA	4	2	FA	14	73	1	T	T	B + M → B	•	1.	7	7	Ť	ৰ ব
Push Data	PSHA	+	+-	+	T	+	†	T	1	t	1	1	t	36	4	1	A → Msp, SP - 1 → SP	1.	•	.	1	7	•
	PSHB	1	T	T	1	1	T	T	T	T	1	1	T	37	4	1,		•	•	٠.	1	Ŧ	1
Pull Data	PULA	1	T	Τ	T	Т	1	T	1	T	T			32	3	1	SP + 1 → SP, Map → A	•	•	·I·	• •	·T·	•1
	PULB	1	\top	1		T	T	T	T	Τ	Τ	Ι	Ι	33	3	1	SP + 1 → SP, Msp → 8	•	•	1	•	·T·	• [
Rotate Left	ROL	Ì	T	T	1	1	1	69	6	2	79	6	73		Г	Т	M	•	•	. 1	1	0	0
	ROLA	+-	1	Ť	\top	1	T	1	+	T	1	Τ	1	49	1	1		•	•	1	1	(8)
	ROLB	+	\dagger	t	†	+	†	1	T	†	1	\top	T	59	1	1	B C 67 60	ŀ	1	1	1	1	9
Rotate Right	ROR	+	十	$^{+}$	+-	+	+	66	6	12	76	6	13	T	Ť	†	м,	1.	1	1	rh	rto	®
	RORA	1	†	†	1	✝	†	1	Ť	1	1-	1	T	46	1	Ťī	- V-C-CITTITIO	•	1	7	1	1	3)
	RORB	+	+	+	+-	+	-†-	+	+	+-	+-	+	+	56	1	٦,	ˈˈa' ˈb' • • • • • • • • • • • • • • • • • • •	١.	٦.	. 1	1	1	8)

(Note) Condition Code Register will be explained in Note of Table 17.

Table 14 Accumulator, Memory Manipulation Instructions

							Add	Iressi	ng f	Mod	es							L°			on (•
Operations	Mnemonic	IMI	MEI	-	DIF	REC	Ţ	IN	DE)	ζ.	EX1	ren	D	IMI	PLIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	*	OP	~	*	OP	~	#	OP	~	#		н	1	N	z	>	C
Shift Left	ASL		Π					68	6	2	78	6	3				м,	•	•	1		6	1
Arithmetic	ASLA	T		Г								Γ		48	1	1]^ [+[]]]]+0	•	•	1		0	
	ASLB		Π	Г			Г						Γ	58	1	1	B C 57 50	•	٠	:	:	⑥	*
Double Shift Left, Arithmetic	ASLD											Г		05	1	1	C A7 A0 87 80	•	•	1	1	6	:
Shift Right	ASR	1	T	Γ			Т	67	6	2	77	6	3			Γ	W)	•	•	1	F	6	1
Arithmetic	ASRA	1	1	Г			T		_	Г			Г	47	1	1	^ + <u> </u> -	•	•	1		⑥	1
	ASRB		T	Г		_	T							57	1	1	1 0' Ed C	٠	•	1	:	⑥	
Shift Right	LSR		T				Г	64	6	2	74	6	3		Г	Γ	M1	•	•	R	1	0	1
Logical	LSRA	1	Γ										Γ	44	1	1 4 0 - 5,7 - 1 - 1 - 1		•	•	R	:	⑥	Ī
	LSRB		Ī	1			T							54	1	1 0-ACC A/ ACC B + A7 A0 87 80	10 0	•	•	R	1	6	
Double Shift Right Logical	LSRD													04	1		•	•	R	;	6	,	
Store	STAA		Г	Г	97	3	2	A7	4	2	67	4	3		Ι	Γ	A → M	•	•	1	1	R	ŀ
Accumulator	STAB		Γ		D7	3	2	E 7	4	2	F7	4	3		Τ	Г	B → M	•	•	1	1	А	ŀ
Store Double Accumulator	STD				00	4	2	ED	5	2	FD	5	3				A → M B → M + 1	•	•	:	1	R	ŀ
Subtract	SUBA	80	2	2	90	3	2	AO	4	2	BO	4	3			L	A - M - A	•	•	ŧ	1:	1:	Ŀ
	SUBB	œ	2	2	00	3	2	ΕO	4	2	FO	4	3			Ι.	0 - M → B	•	•	ŧ	1	ı	Γ
Double Subtract	SUBD	83	3	3	93	4	2	A3	5	2	83	5	3			Ī	A:B-M:M+1-A:B	•	•	\$	[t	1	ŀ
Subtract Accumulators	SBA													10	1	•	A - B → A	•	·	:	ı	ŧ	ŀ
Subtract	SBCA	82	2	1.	92		2	A2		2	82	4	3		L	L	A - M - C → A	•	ŀ	ŧ	1	:	L
With Carry	SBCB	C2	2	2	02	3	2	E2	4	2	F2	4	3				B - M - C → B	٠	•	ŧ	:	1	L
Transfer	TAB	1_	┖	L	L_	╙	L	<u> </u>	L	L	_	_	1.	16	1	1	A→B		•	1	1	R	ŀ
Accumulators	TBA	↓_	L	<u> </u>		_	L	<u> </u>	L	L	ㄴ	┖	L	17	1	1	B → A	ŀ	ŀ	!	1	R	ŀ
Test Zero or	TST	1	L	_		┖	L	60	4	2	70	4	3	<u></u>	L	M - 00 1 A - 00 1 B - 00	M - 00	ŀ	•	1	1	R	ľ
Minus	TSTA	L	L	L	L.	L	L	L	L	L	L	\perp	L	40	1		<u> </u>	ŀ	٠	1:	1:	R	ľ
	TSTB		L	L	L		L	<u> </u>	L	L	<u> </u>	L	L	5D	1			<u> •</u>	Ŀ	1:	1.	P	Ľ
And Immediate	AIM		L		71	6	3	61	7	3			L			M+IMM-M •		•	•	1	1	R	l
QR Immediate	OIM				72	6	3	62	7	3			L		L			•	1	1	R	L	
EOR Immediate	EIM		Γ		75	6	3	65	7	3	\Box	Ĺ	Ľ					•	ī	:	R	ľ	
Test Immediate	TIM	T	Γ	T	7B	4	13	68	5	3	T-	Γ	T		1		M-IMM		١.	1	1	R	T

(Note) Condition Code Register will be explained in Note of Table 17.

Additional Instruction

In addition to the HD6801 instruction set, the HD63701X0 prepares the following new instructions.

$$AIM.....(M)\cdot(IMM) \rightarrow (M)$$

Executes "AND" operation to immediate data and the memory contents and stores its result in the memory.

$$OIM.....(M) + (IMM) \rightarrow (M)$$

Executes "OR" operation to immediate data and the memory contents and stores its result in the memory.

$$EIM \dots (M) \oplus (IMM) \rightarrow (M)$$

Executes "EOR" operation to immediate data and the memory contents and stores its result in the memory.

$$TIM \dots (M) \cdot (IMM)$$

Executes "AND" operation to immediate data and changes the relative flag of the condition code register.

These area 3-byte instructions; the first byte is op code, the second immediate data and the third address modifier.

$$XGDX.....(ACCD) \rightarrow (IX)$$

Exchanges the contents of accumulator and the index register.

SLP

Goes to the sleep mode. Refer to "LOW POWER DIS-SIPATION MODE" for more details of the sleep mode.

Table 15 Index Register, Stack Manipulation Instructions

							Add	iress	ing	Мо	des						Boolean/	۲			on (•
Painter Operations	Mnemonic	IM	ME	D	DI	REC	:т	IN	DE:	×	EX	TEN	D	IMP	LIE	D	Arithmetic Operation	5	4	3	2	1	ò
		OP	-	#	OP	~	*	OP	~	*	OР	-	*	OP	~	*		I	-	N	Z	$\overline{\mathbf{v}}$	Ç
Compare Index Fleg	CPX	BC	3	3	9C	4	2	AC	5	2	BC	5	3			Γ	X-M:M+1	•	•	:	1		:
Decrement Index Reg	DEX									T		1		09	1	1	X - 1 → X	•	•	•	1	•	•
Decrement Stack Potr	DES	1	Г			Г	Г			Г		Π		34	1	1	SP - 1 - SP	•	٠	•	•	•	•
Increment Index Reg	INX	1		_			Ī		Π	Г				08	1	ī	X + 1 → X	•	•	•	#	•	٠
Increment Stack Potr	INS		Г	Ī		Ī	T	_						31	1	1	SP + 1 → SP	•	٠	•	٠	•	•
Load Index Reg	LDX	CE	3	3	ĐΕ	4	2	€€	5	2	FE	5	3				$M \rightarrow X_H$, $(M+1) \rightarrow X_L$	•	•	7	1	A	٠
Load Stack Potr	LDS	BΕ	3	3	9E	4	2	ΑE	5	2	BΕ	5	3				M - SPH. (M+1) - SPL	•	٠	Ĩ,	1	R	Ŀ
Store Index Reg	STX				DF	4	2	EF	5	2	FF	5	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$	•	•	7,	:	A	•
Store Stack Pntr	STS	Т			9F	4	2	AF	5	2	B₽	5	3				SP _H → M, SP _L → (M+1)	•	•	7	:	R	•
Index Reg → Stack Pntr	TXS	Τ.	Г	Ī		Τ	Т		Т					35	1	1	X - 1 → SP	•	•	•	•	•	•
Stack Pntr - Index Reg	TSX	1	t	T	\vdash	T	T			1				30	1	1	SP + 1 → X	•	•	•	•	•	1
Add	ABX	1	Т	T		T		Г				Γ		3A	1	٦	8 + X → X	•	•	•	•	•	ŀ
Push Data	PSHX	7	Г			Г	Π	Г	Т			Г		3C	5	ī	X _L → M _{ND} , SP - 1 → SP	•	•	•	•	•	ŀ
		1			1	1				l		1				1	X _H → M _{sp} , SP = 1 → SP					Ĺ	
Pull Data	PULX	1	Γ	T		T	Π			Г	T	Γ	Γ	38	4	1	SP + 1 → SP, M _{SP} → X _H	•	•	•	•	•	1
						1									1	l	SP + 1 → SP, Map → XL			١.	l	L_	L
Exchange	XGDX	1	Π	1	1	Т	1	1	T	Π		Г	Π	18	2	1	ACCDIX	•	•	•	•		Г

(Note) Condition Code Register will be explained in Note of Table 17.

Table 16 Jump, Branch Instruction

							Ad	dress	ung	Мо	des							7		diti Reg			e
Operations	Mnemonic	REL	ATI	VE	DII	₹EC	:т	IN	DE:	×	EXT	ŒΝ	D	IMP	LIE	D	Branch Test	5	4	3	2	ī	0
		OP	~	#	OP	~		OP	~	#	ОP	~	*	OР	~	*		H	_	2	Z	>	С
Branch Always	BRA	20	3	2													None	•	•	٠	•	٠	•
Branch Never	BRN	21	3	2								[None	•	•	•	•	•	•
Branch If Carry Clear	BCC	24	3	2	I												C • 0	•	•	•	•	•	•
Branch If Carry Set	BCS	25	3	2						Г							C = 1	•	•	•	•	•	•
Brench If = Zero	BEQ	27	3	2									Г				Z = 1	•	•	٠	•	•	•
Branch If > Zero	BGE	2C	3	2	T					Г			Г				N ⊕ V • 0	•	•	•	•	٠	•
Branch If > Zero	8GT	2E	3	2							Γ						Z + (N @ VI - 0	•	•	٠	•	٠	•
Branch If Higher	вні	22	3	2									Г				C+Z • 0	•	•	٠	•	٠	•
Branch If < Zero	BLE	2F	3	2		П		Γ				Г	П				Z + (N @ V) = 1	•	•	•	•	•	•
Branch If Lower Or Same	BLS	23	3	2			Γ										C + Z = 1	•	•	•	•	•	•
Branch If < Zero	BLT	20	3	2	Т		Г		Г								N ⊕ V • 1	•	•	•	•	•	•
Branch If Minus	BMI	28	3	2			Г		Г			Ι_					N = 1	•	•	•	•	•	•
Brench If Not Equal Zero	BNE	26	3	2													z - o	•	•	•	•	•	•
Brench If Overflow Clear	BVC	28	3	2													V-0	•	•	•	•	•	٠
Branch If Overflow Set	BVS	29	3	2											L		V = 1	•	•	٠	•	•	·
Branch If Plus	BPL	2A	3	2			L		L		<u> </u>	L	L		L		N = 0	•	•	•	•	·	·
Branch To Subroutine	BSR	8D	5	2		1									Г			•	•	•	•	•	•
Jump	JMP	1				Г	Г	6E	3	2	7 E	3	3		Г		1	•	•	•	•	•	•
Jump To Subroutine	JSR	1	Π	Г	90	5	2	AD	5	2	BD	6	3		Г	Π		•	•	•	•	•	•
No Operation	NOP													01	1	,	Advances Prog. Cntr. Only	•	•	•	•	•	•
Return From Interrupt	RTI		Γ	Γ			Γ	1					L	38	10	1		Ŀ	-	(ì	=	-
Return From Subroutine	ATS	Ī	Γ										Ĺ	39	5	1		•	•	•	•	·	•
Softwere Interrupt	SWI	Ι			Ι.					Γ			Γ	3F	12	1		•	s	•	•	•	•
Wait for Interrupt®	WAI		T	Γ			Ι		Γ	Ι	I	L	Ι	3E	9	ļ١]	•	3,	•	•	•	•
Sleep	SLP	\top	1	Т	Τ-		ī	T	П	1	1	Г	T	1A	4	1		•		•	•	•	•

(Note) * WAI put R/W high; Address Bus goes to FFFF; Data Bus becomes tri-stated.

Condition Code Register will be explained in Note of Table 17.

Table 17 Condition Code Register Manipulation Instructions

		Addre	ssing8	Aodes		C	ondit	ion C	ode	Regist	te/
Operations	Mnemonic	IM	PLIE	D	Boolean Operation	5	4	3	2	1	0
		QP.	~	•		н	1	N	Z	×	С
Clear Carry	CLC	oc	1	1	0 → C	•	•	•	·	•	R
Clear Interrupt Mask	CLI	OE	1	1	0 → 1	•	R	•	•	•	·
Clear Overflow	CLV	OA	1	1	0 - V	•	•	•	•	R	Ŀ
Set Carry	SEC	00	1	1	1 → C	•	•	•	•	•	5
Set Interrupt Mask	SEI	0F	1	1	1 1	•	S	•	ŀ	•	Ŀ
Set Overflow	SEV	OB	1	•	1 → V	•	•	•	<u> </u>	S	Ŀ
Accumulator A → CCR	TAP	06	1	1	A - CCR			(10 -	_	_
CCR → Accumulator A	TPA	07	1	1	CCR → A	•	•	•	•	•	<u> </u>

LEGEND

- OP Operation Code (Hexadecimal)
- Number of MCU Cycles
- MSP Contents of memory location pointed to by Stack Pointer
- Number of Program Bytes
- Arithmetic Plus
- **Arithmetic Minus**
- Boolean AND
- Boolean Inclusive OR
- Boolean Exclusive OR
- Complement of M
- Transfer into
- Bit = Zero
- 00 Byte = Zero

CONDITION CODE SYMBOLS

- Half-carry from bit 3 to bit 4
 - Interrupt mask
 - Negative (sign bit)
 - Zero (byte)
- Overflow, 2's complement Carry/Borrow from/to bit 7
- Reset Always
- Set Always
- Set if true after test or clear
- Not Affected

(Note) Condition Code Register Notes: (Bit set if test is true and cleared otherwise)

- Test: Result = 10000000? (1) (Bit V)
- (2) Test: Result \ 00000000? (Bit C)
- Test: BCD Character of high-order byte greater than 10? (Not cleared if previously set) (3) (Bit C)
- (4) (Bit V) Test: Operand = 10000000 prior to execution?
- (5) (Bit V) Test: Operand = 011111111 prior to execution?
- (6) (Bit V) Test: Set equal to N@ C = 1 after the execution of instructions
- (7) (Bit N) Test: Result less than zero? (Bit 15=1)
- (8) (All Bit) Load Condition Code Register from Stack.
- Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exist the wait state. (Bit I)
- Set according to the contents of Accumulator A. (All Bit)
- Result of Multiplication Bit 7=1? (ACCB) (Bit C)

Table 18 OP Code Map

OF	, ,					ACC	ACC		EXT		ACCA	or SP		Ι	ACCE	or X]
COL	- 1					A	В	IND	DIR.	IMM	DIR	IND	EXT	IMM	DIR	IND	EXT]
<	ŧi	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111]
10	\setminus	0	1	2	3	4	5	6	7	8	9	A	В	С	٥	Ε	F	L
0000	o		SBA	BRA	TSX		N	EG						UB				0
0001	1	NOP	CBA	BRN	INS			A	IM					MP				1
0010	2			вні	PULA			0	IM				S	BC				12
0011	3			BLS	PULB		C	MC			SU	/BD		<u> </u>	AC	DD		3
0100	4	LSRD		BCC	DES		LSR							ND.				14
0101	5	ASLD		BCS	TXS	EIM							Е	II T				15
0110	6	TAP	TAB	BNE	PSHA		ROR						L	DA				6
0111	7	TPA	TBA	BEQ	PSHB		A	SR				STA			L	STA		7
1000	0	INX	XGDX	BVC	PULX		A	SL						OR				18
1001	9	DEX	DAA	BVS	RTS		R	OŁ					A	DC				9
1016	A	CLV	SLP	BPL.	ABX		Đ	EC					O	RA				A
1011	В	SEV	ABA	ВМІ	RTI			1	IM				А	DD				В
1100	c	CLC		BGE	PSHX		II	NC			С	PX		l	L	DD		C
1101	o	SEC		BLT	MUL	TST				BSR		JSR				STD		D
1110	E	CLI		BGT	WAI			J	MP		Ĺ	DS			L	DX		Ε
1111	F	SEI		BLE	SWI		C	LR			1	STS				STX		F
	_	0	٦.	2	3	4	5	6	7	8	9	A	В	С	D	E	F	J

UNDEFINED OF CODE

^{*} Occurs only on each instruction of AIM, OIM, EIM, TIM

■ CPU OPERATION

CPU Instruction Flow

When operating, the CPU fetches an instruction from a memory and executes the required functions. This sequence starts after the reset release and repeats itself limitlessly if not affected by a special instruction or a control signal. SWI, RTI, WAI and SLP instructions are to change this operation, while NMI, IRQ, IRQ, HALT and STBY are to control it. Fig. 28 gives the CPU mode shift and Fig. 29 the CPU system flow-chart. Table 19 shows the CPU operating states and port states.

Operation at Each Instruction Cycle

Table 20 provides the operation at each instruction cycle. By the pipeline control of the HD63701XO, MULT, PUL, DAA and XGDX instructions etc. prefetch the next instruction. So attention is necessary to the counting of the instruction cycles because it is different from the existent one from op code fetch to the next instruction op code.

Table 19 CPU Operation State and Port State

Port	Mode	Reset	STBY***	HALT***	Sleep
Port 1	Mode 1, 2	н	-	т	н
(A, ~ A,)	Mode 3	T	- T		Keep
	Mode 1, 2	Т	т	Keep	Keep
Port 2	Mode 3	1 '	•		Keep
Port 3	Mode 1, 2	т	7	Т	Т
(D, ~D,)	Mode 3	1 '	,		Keep
Port 4	Mode 1, 2	Н		Т	Н
(A. ~ A.s)	Mode 3	Т	1 '		Keep
	Mode 1,2	7	Т	T	т
Port 5	Mode 3	1 '_	'		<u> </u>
	Mode 1, 2		т	Кеер	Keep
Port 6	Mode 3	1 '			1 Keep
	Mode 1, 2	•	т	•••	•
Port 7	Mode 3	Т	7 '		Keep

H; High, L; Low, T; High Impedance

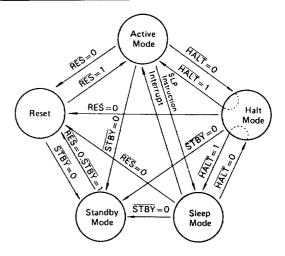


Figure 28 CPU Operation Mode Transition

[•] RD, WR, A/W, LIR-H, BA-L

^{**} RD, WR, R/W-T, LIR, BA-H

^{****} HALT is unacceptable in mode 3.
**** E pin goes to high impedance state.

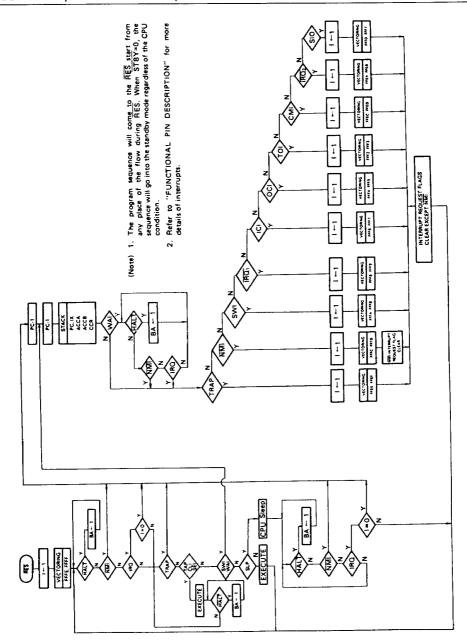


Figure 29 HD63701X0 System Flow Chart

Table 20 Cycle-by-Cycle Operation

	s Mode &	Cycles	Cycle	Address Bus	R/W	RD	WR	LIR	Data Bus
instr	uctions		الــــــا						L
MMEDIA	ATE								
ADC	ADD		1	Op Code Address + 1	1	0	1	1	Operand Data
AND	BIT	i	2	Op Code Address + 2	1	0	1	0	Next Op Code
CMP	EOR	2			l l				i
LDA	ORA	1			İ	i '			}
SBC	SUB								
ADDD	CPX	1	1	Op Code Address + 1	1	0	1	1	Operand Data (MSB)
LDD	LDS	3	2	Op Code Address + 2	1	0	1	1	Operand Data (LSB)
LDX	SUBD	ļ	3	Op Code Address + 3	1	0	1	0	Next Op Code
HRECT									
ADC	ADD	т	1	Op Code Address + 1	1	0	1	1	Address of Operand (LSB
AND	BIT	!	2	Address of Operand	1	ō	1	1	Operand Data
CMP	EOR	3	3	Op Code Address + 2	1	ō	1 1	0	Next Op Code
LDA	ORA	ľ	ľ	Op Code Rodross : 2		_			1
SBC	SUB					1	ł	ĺ	
STA	300	+	1	Op Code Address + 1	+	0	1 1	1	Destination Address
314		3	2	Destination Address	1 0	l i	0	1 1	Accumulator Data
		"	3	On Code Address + 2	1 1	1 6	l ī	0	Next Op Code
ADDD	CPX	+	1	Op Code Address + 1	+	0	1	1	Address of Operand (LSB
LDD	LDS	1.	2	Address of Operand	1	0	1	l i	Operand Data (MSB)
LDX	SUBD	4	3	Address of Operand + 1	1	0	1 1	1	Operand Data (LSB)
LUX	3000		4	Op Code Address + 2	1	0	1 ,	0	Next Op Code
STD	STS	+	1-7-	Op Code Address + 1	1-1-	0	1	1	Destination Address (LSB
STX	313	Ì	2	Destination Address	o	l ĭ	0	l i	Register Data (MSB)
317		4	3	Destination Address + 1	0	١.	0	1 1	Register Data (LSB)
		1	1 4	Op Code Address 1 2	Ĭ	0	i	0	Next Op Code
JSR		+	1	On Code Address + 1	1	0	1-1	1	Jump Address (LSB)
3311		1	2	FFFF	l i	1	1	1 3	Restart Address (LSB)
		5	3	Stack Pointer	1 0	1	0	1	Return Address (LSB)
		ľ	4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
		1	5	Jump Address	1	0	1	0	First Subroutine Op Code
TIM			1	Op Code Address + 1	1	0	1	1	Immediate Data
			2	Op Code Address + 2	1	0	1	1	Address of Operand (LSI
		4	3	Address of Operand	l i	0	1	1	Operand Data
			4	Oo Code Address + 3	1 1	0	1	0	Next Op Code
AIM	EIM	+	 i	Op Code Address + 1	1	0	1 1	1	Immediate Data
OIM	L		2	Op Code Address + 2	1	0	1 1	1 1	Address of Operand (LS
3141			3	Address of Operand	1	0	1	1	Operand Data
		6	4	FFFF	1	1	1	1	Restart Address (LSB)
			5	Address of Operand	0	1	0	1	New Operand Data
		1	6	Op Code Address + 3	1 1	0	l i	1 0	Next Op Code

Address M Instruc		Cycles	Cycle	Address Bus	R∕₩	RD	WR	[IR	Data Bus
NDEXED									
JMP		Τ	1	Op Code Address + 1	1	0	1	1	Offset
•		3	2	FFFF	1	1	1	1	Restart Address (LSB)
		1	3	Jump Address	1	0	1	0	First Op Code of Jump Routine
ADC A	NDD .	 	1	Op Code Address + 1	1	0	1	1	Offset
	SIT	1	2	FFFF	1	1	1	1	Restart Address (LSB)
	OR		3	IX + Offset	1	0	1	1	Operand Data
	ARC	4	4	Op Code Address + 2	1	0	1	0	Next Op Code
	SUB	1							
TST									
STA		+	1	Op Code Address + 1	1	0	1	1	Offset
		Ι.	2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	IX + Offset	0	1	0	1	Accumulator Data
			4	Op Code Address + 2	1	0	1	0	Next Op Code
ADDD		 	1	Op Code Address + 1	1	0	1	1	Offset
	.DD	i	2	FFFF	1	1	- 1	1	Restart Address (LSB)
	DX	5	3	IX + Offset	1	0	1	1	Operand Data (MSB)
SUBD			4	IX + Offset + 1	1	0	1	1	Operand Data (LSB)
		1	5	Op Code Address + 2	1	0	1	0	Next Op Code
STD S	STS	t -	1	Op Code Address + 1	1	0	1	1	Offset
STX		i	2	FFFF	1	1	1	1	Restart Address (LSB)
0.17		5	3	IX + Offset	١٥	1	Ιo	1	Register Data (MSB)
		1	4	IX + Offset + 1	0	1	٥	1	Register Data (LSB)
		1	5	Op Code Address + 2	1	0	1	0	Next Op Code
JSR		+	1	Op Code Address + 1	1	0	1	1	Offset
			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer	0	1	0	1	Return Address (LSB)
		-	4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
			5	IX + Offset	1	0	1	0	First Subroutine Op Code
ASL A	ASR	1	1-1-	Op Code Address + 1	1	0		1	Offset
	DEC		2	FFFF	1	1	1	1	Restart Address (LSB)
	SR	1 .	3	IX + Offset	1 1	0	1 1	1	Operand Data
	BOL	6	4	FFFF	1	1	1	1	Restart Address (LSB)
ROR		1	5	1X + Offset	0	1	0	1	New Operand Data
		1	6	Op Code Address + 1	1	0	1	0	Next Op Code
ŤIM			1	Op Code Address + 1	1	0	1	1	Immediate Data
			2	Op Code Address + 2	1 1	0	1	1	Offset
		5	3	FFFF	1	1	1	1	Restart Address (LSB)
		1	4	IX + Offset	1	0	1	1	Operand Data
			5	Op Code Address + 3	1	0	1	0	Next Op Code
CLR		† · · · · ·	1	Op Code Address + 1	1	0	1	1	Offset
			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	IX + Offset	1	0	1	1	Operand Data
		1	4	IX + Offset	0	1	0	1	00
		1	5	Op Code Address + 2	1	0	1	0	Next Op Code
AIM E	MI		1	Op Code Address + 1	i i	0	ī	1	Immediate Data
OIM			2	Op Code Address + 2	1	0	1	1	Offset
		1	3	FFFF	1	1	1	1	Restart Address (LSB)
		7	4	IX + Offset	1	0	1	1	Operand Data
		1	5	FFFF	1	1	1	1	Restart Address (LSB)
			6	IX + Offset	0	1	0	1	New Operand Data
		1	7	Op Code Address + 3	1	0	1	0	Next Op Code

Address Mo Instruction		Cycles	Cycle #	Address Bus	R/W	RD	WR	LiR	Data Bus
XTEND									
JMP			1	Op Code Address + 1	1	0		1	Jump Address (MSB)
		3	2	Op Code Address + 2	1 1	0	1	1	Jump Address (LSB)
			3	Jump Address	1	0	1	0	Next Op Code
ADC ADD	TST		1	Op Code Address + 1	1	0	1	1	Address of Operand (MSB
AND BIT		l . I	2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB)
CMP EOR		4	3	Address of Operand] 1	0	1	1	Operand Data
LDA ORA			4	Op Code Address + 3	1	0	1	0	Next Op Code
SBC SUB		1	i 1				1		
STA		 	-	Op Code Address + 1	1	0	1	1	Destination Address (MSB
•		l .	2	Op Code Address + 2	1	0	1	1	Destination Address (LSB)
		4	3	Destination Address	0	1	0	1	Accumulator Data
		1	4	Op Code Address + 3	1	0	1	0	Next Op Code
ADDD		 	1	Op Code Address + 1	17	0	1	1	Address of Operand [MSI
CPX LD	n	}	2	Op Code Address + 2	1 1	. 0	1	1	Address of Operand (LSB)
LDS LD		5	3	Address of Operand	1 1	0	1	1	Operand Data (MS8)
SUBD	^	"	4	Address of Operand + 1	1	0	1	1	Operand Data (LSB)
3000		1	5	Op Code Address + 3	1	0	1	0	Next Op Code
STD ST	· ·	 	1	Op Code Address + 1	1	0	1	1	Destination Address (MSI
STX	•	1	2	On Code Address + 2	1	١٥	1	1	Destination Address (LSB
5		5	3	Destination Address	0	1	0	1	Register Data (MSB)
		"	4	Destination Address + 1	0	1	0	1	Register Data (LSB)
			5	On Code Address + 3	1 1	0	1	0	Next Op Code
JSR		+	1	Op Code Address + 1	+ + + +	0	1	1	Jump Address (MSB)
3311			2	Op Code Address + 2	1 1	۱ ۰	1	1	Jump Address (LSB)
			3	FFFF	1	l 1	1	1	Restart Address (LSB)
		6	4	Stack Pointer	0	1	0	1	Return Address (LSB)
			5	Stack Pointer - 1	ì	1	0	1	Return Address (MSB)
		1	6	Jump Address	1	١٥	Ιi	0	First Subroutine Op Code
ASL AS		+	1 1	Op Code Address + 1	-	0	1	1	Address of Operand (MS)
COM DE			2	Op Code Address + 2	1	o	1	1	Address of Operand (LSB
INC LS		Į	3	Address of Operand	1 1	l o	1	1 1	Operand Data
NEG RO		6	4	FFFF	1 ;	,	1 ;	l i	Restart Address (LSB)
	J L		5	Address of Operand	ا	l i	0	1	New Operand Data
ROR			6	Op Code Address + 3	l ĭ	ا أ	1	o	Next Op Code
CLB		-	1	Op Code Address + 1		l ŏ	+ + + + -	1 1	Address of Operand (MS
CLR		1	2	Op Code Address + 2	i	lő	1	1 1	Address of Operand (LSE
		_ ا	3	Address of Operand	1 ;	0	1 ;	1 ;	Operand Data
		5	1 -		ò	l ĭ	0	Ιí	00
		1	5	Address of Operand Op Code Address+3	1	اها	1 1	۱ ۵	Next Op Code

	Mode &	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
7130			لبتيا						
IMPLIED									
ABA	ABX		1	Op Code Address + 1	1	0	1	0	Next Op Code
ASL	ASLD								
ASR	CBA	i I							
CLC	CLI		li						
CLR	CLV				1				
COM	DEC								
DES	DEX				1				
INC	INS	1							
INX	LSR	1							
LSRD	ROL	1				ł			
ROR	NOP	1	ŀ		1	l			
SBA	SEC				ł	1			
SEI	SEV)			
TAB	TAP	1]		į .	1			
TBA	TPA	i				l	1		
TST	TSX		i			1			
TXS		1			1			1	
DAA	XGDX	 	1	Op Code Address + 1	1	0	1	0	Next Op Code
		2	2	FFFF	1	1	1	1	Restart Address (LSB)
PULA	PULB	+	1	Op Code Address + 1	1	0	1	0	Next Op Code
		1 3	2	FFFF	1	1	1 1	1	Restart Address (LSB)
		-	3	Stack Pointer + 1	1	0	1	1	Data from Stack
PSHA	PSH8	+	1	Op Code Address + 1	1	0	1	1	Next Op Code
		1 .	2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	Stack Pointer	0	1	0	1	Accumulator Data
		ŀ	4	Op Code Address + 1	1	0	1	0	Next Op Code
PULX		 	7	Op Code Address + 1	1	0	1	0	Next Op Code
		1 .	2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	Stack Pointer + 1	1	0	1	1	Data from Stack (MSB)
		1	4	Stack Pointer + 2	1	0	1	1	Data from Stack (LSB)
PSHX		1	1	Op Code Address + 1	1	0	1	1	Next Op Code
		1	2	FFFF	1	1	1 1	1	Restart Address (LSB)
		5	3	Stack Pointer	0	1	0	1	Index Register (LSB)
			4	Stack Pointer - 1	1 0	1	0	1	Index Register (MSB)
		1	5	Op Code Address + 1	1	0	1	0	Next Op Code
RTS		+	1	Op Code Address + 1	- - - - - - - - - - 	0	1	1	Next Op Code
			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer + 1	1	0	1	1	Return Address (MSB)
			4	Stack Pointer + 2	1	0	1	1	Return Address (LSB)
		1	5	Return Address	1	0	1	0	First Op Code of Return Routine
MUL		1	1	Op Code Address + 1	1	0	1 "	0	Next Op Code
]	2	FFFF	1	1	1	1	Restart Address (LSB)
		1	3	FFFF	1	1	1	1	Restart Address (LSB)
		7	4	FFFF	1	1	1	1	Restart Address (LSB)
		1	5	FFFF	1	1	1	1	Restart Address (LSB)
		į	6	FFFF	1	1	1	1	Restart Address (LSB)
		i	1 7	FFFF	1		1 1	l i	Restart Address (LS8)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/₩	RD	WR	LIR	Data Bus
MPLIED								
WAI	T	1	Op Code Address + 1	1	0	1	1	Next Op Code
	i	2	FFFF	1	1	1	1	Restart Address (LSB)
	i	3	Stack Pointer	0	1	0	1	Return Address (LSB)
	1	4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
	9	5	Stack Pointer - 2	0	1	0	1	Index Register (LSB)
		6	Stack Pointer 3	0	1	0	1	Index Register (MSB)
	ļ	7	Stack Pointer - 4	0	1	0	1	Accumulator A
	i	8	Stack Pointer – 5	0	1	0	1	Accumulator 8
		9	Stack Pointer – 6	0	0	1	1-	Conditional Code Register Next Op Code
RTI		1	Op Code Address + 1	1			;	Restart Address (LSB)
	1	2	FFFF	1	1	!		Conditional Code Register
		3	Stack Pointer + 1	1	0	1	l ;	Accumulator B
		4	Stack Pointer + 2	1	0	i ;		Accumulator A
	10	5	Stack Pointer + 3	1	0	l i	1	Index Register (MSB)
	'	6	Stack Pointer + 4	1	1 -	1 ;	1	
	ì	7	Stack Pointer + 5	1	0	;	;	Index Register (LSB) Return Address (MSB)
	1	8	Stack Pointer + 6	1			;	Return Address (LSB)
	1	9	Stack Pointer + 7	!	0	;	0	First Op Code of Return Routin
		10	Return Address	1	0		1	
SWI		1	Op Code Address + 1	1	_	1 !	1 -	Next Op Code
		2	FFFF	1	!	1	!	Restart Address (LSB)
		3	Stack Pointer	0	1 !	0	1	Return Address (LSB)
	1	4	Stack Pointer 1	0	1 1	0	!	Return Address (MSB)
	1	5	Stack Pointer - 2	0	!	0	1 1	Index Register (LSB)
	12	6	Stack Pointer - 3	0	1	0	1	Index Register (MSB)
	'-	7	Stack Pointer 4	0	1 1	0	1 !	Accumulator A
	1	8	Stack Pointer - 5	0	1	0	!	Accumulator B
		9	Stack Pointer - 6	0	1	0		Conditional Code Register
		10	Vector Address FFFA	1	0	1		Address of SWI Routine (MSB
	1	11	Vector Address FFFB	1	0	;	0	Address of SWI Routine (LSB) First Op Code of SWI Routine
		12	Address of SWI Routine	1_1_		1	1 -1	Next Op Code
SLP		1	Op Code Address + 1	1	0	1	;	
		2	FFFF	!	1 !	1	1 :	Restart Address (LSB)
						1 1		
	۱ ۵	Sleep			1 1	1	1 1	\
	1	July		1		1		l í
		1			1 :	1 :	:	Restart Address (LSB)
		3	FFFF	1 !	0	;	0	Next Op Code
	—	4	Op Code Address + 1	1		<u> </u>	1 0	Next Op Code
RELATIVE								
BCC BCS	1	1 1	Op Code Address + 1	1	0	1	1	Branch Offset
BEQ BGE	3	2	FFFF	1	1	1	1	Restart Address (LSB)
BGT BHI	1		Branch Address Test = 11	١,	0	1	١,	First Op Code of Branch Rout
BLE BLS		3	Op Code Address + 1 Test = "0"	1 '	١ '	'	1 0	Next Op Code
BLT BMT		1	1	1	i	1		
BNE BPL		1	1	1	1	-		
BRA BRN		1	1	1	1	1	1	
BVC BVS	l	i	1	1	1	1	1.	
BSA		1	Op Code Address + 1	1	0	1	1	Offset
		2	FFFF	1	1	1	1	Restart Address (LSB)
	5	3	Stack Pointer	0	1	0	1	Return Address (LSB)
		4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
		5	Branch Address	1	1 0	1 1	0	First Op Code of Subroutine

■ DIFFERENCES BETWEEN HD63701X0 AND HD6301X0

Item	HD63701X0			HD6301X0				
V _{PP} /OE pin function	V _{PP} /OE MCU mode; Connected to V _{SS} voltage PROM mode; Input for the programming voltage				V _{SS} Connected to V _{SS} Voltage			
Input capacitance	V _{PP} /OE, 25pF max All other inputs, 12.5pF max				All inputs, 12.5pF max			
Input high voltage of MP ₀ , MP ₁	$V_{IH} = V_{SS} - 0.5V \text{ min}$			V _{IH} = 2.0V min				
Bus Timing • Address, R/W, hold timing • Data hold timing	HD63701X0	HD637A01X0	HD637B01X0		HD6301X0	HD63A01X0	HD63B01X0	
	t _{AH} 70	45	30	t _{AH}	80	50	35	
	t _{HW} 70	50	35	t _{HW}	80	50	40	
	Unit: ns						Unit: ns	
Crystal oscillator characteristics	Internal resistance of crystal oscillator RS Frequency (MHz) 2.5 4.0 6.0 8.0			Internal resistance of crystal oscillator R_S $R_S = 60\Omega$ max				
	R _S max (Ω)	500 12						
Storage temperature	$T_{\text{stg}} = -55 \text{ to } 125 ^{\circ}\text{C}$			$T_{\text{stg}} = -55 \text{ to } 150^{\circ}\text{C}$				
Caution	The HD63701X0 differs from HD6301X0 in chip design and manufacturing process. When applying the HD63701X0 system to HD6301X0, and HD6301X0 system to HD63701X0, note that characteristic values are not exactly the same even if guaranteed values are the same.							

■ PRECAUTION TO THE BOARD DESIGN OF OSCILLATION CIRCUIT

As shown in Fig. 30, there is a case that the cross talk disturbs the normal oscillation if signal lines are put near the oscillation circuit. When designing a board, pay attention to this. Crystal and C_L must be put as near the HD63701X0 as possible.

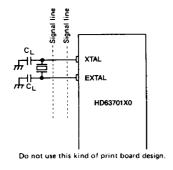


Figure 30 Precaution to the board design of oscillation circuit

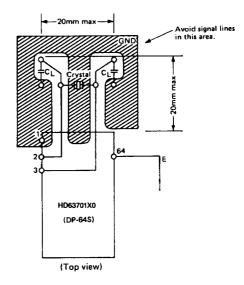


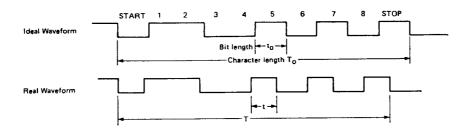
Figure 31 Example of Oscillation Circuits in Board Design

RECEIVE MARGIN OF THE SCI

Receive margin of the SCI contained in the HD63701X0 shown in Table 21.

Note: SCI = Serial Communication Interface

Table 21				
Bit distortion tolerance (t-to)/to	Character distortion tolerance (T-To) /To			
±43.7%	±4.37%			



■ WARNING CONCERNING WAI INSTRUCTION

If the HALT signal is accepted by the MCU while the WAI instruction is executing, the CPU will not operate correctly after HALT mode is canceled.

WAI is a instruction which waits for an interrupt. The corresponding interrupt routine is executed after an interrupt occurs.

However, during the execution of the WAI instruction, HALT input makes the CPU malfunction and fetch an abnormal interrupt vectoring address.

In HALT mode, the CPU operates correctly without the WAI instruction and WAI is executed correctly without HALT input. Therefore, if HALT input is necessary, make interrupts wait during the loop routine, as shown in Figure 32.

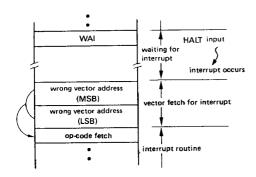


Figure 32 MAC function during WAI

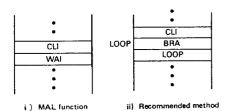


Figure 33 Program to wait for interrupt

WARNING CONCERNING POWER START-UP

RES must be held low for at least 20 ms when the power starts up. In this case, the internal reset function is not effective until the oscillation begins at power-on. The \overline{RES} signal is input to the LSI in synchronism with the internal clock (shown in Figure 33).

Therefore, after power starts up, the LSI conditions such as its I/O ports and operating mode, are unstable. Fix the level of I/O ports by means of an external circuit to determine the level for system operation during the oscillator stabilization time.

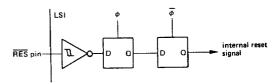


Figure 33 RES circuit

■ WRITE-ONLY REGISTER

When the CPU reads a write-only register, the read data is always SFF, regardless of the value in the write-only register. Therefore, be careful of the results of instructions which read write-only register and perform an arithmetic or logical operation on its contents, such as AIM, ADD, or ROL, is executed, because the arithmetic or logical operation is always done with the data \$FF. In particulars, don't use the AIM, OIM or EIM instruction to manipulate the DDR bit of PORT.